

SSD1677

Advance Information

**960 Source x 680 Gate Red/Black/White
Active Matrix EPD Display Driver with Controller**

This document contains information on a new product. Specifications and information herein are subject to change without notice.

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SSD1677

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1 General Description

The SSD1677 is an Active Matrix EPD Display Driver with Controller which can support Red/Black/White. It consists of 960 source outputs, 680 gate outputs, 1 VCOM and 1 VBD for border that can support a maximum display resolution 960x680.

The SSD1677 embeds booster, regulators and oscillator. Data/Commands are sent from general MCU through the hardware selectable Serial peripheral.

2 Features

- Design for dot matrix type active matrix EPD display
- Support Red/Black/White mono color
- Resolution: 960 source outputs; 680 gate outputs; 1 VCOM; 1VBD for border
- Power supply:
 - VCI: 2.2 to 3.3V
 - VDDIO: Connect to VCI
 - VDD: 1.8V, regulate from VCI supply
- On chip display RAM
 - Mono B/W: 960x680 bits
 - Mono Red: 960x680 bits
- On-chip booster and regulator for generating VCOM, Gate and Source driving voltage
- Gate driving output voltage:
 - 2 levels output (VGH, VGL)
 - Max 40Vp-p
 - VGH: 15V to 20V; VGL: -VGH
 - Voltage adjustment step: 500mV
- Source / VBD driving output voltage:
 - 4 levels output (VSH1, VSS, VSL, and VSH2)

- | |
|--|
| <ul style="list-style-type: none">• VSH1: 9V to 17V (200mV for 9V to 17V)• VSH2: 2.4V to 17V (Voltage step: 100mV for 2.4V to 8.8V, 200mV for 8.8V to 17V)• VSL: -9V to -17V (Voltage step: 500mV) |
|--|

- | |
|---|
| <ul style="list-style-type: none">• |
|---|

- VCOM output voltage

DCVCOM	ACVCOM
-4V to -0.1V in 100mV resolution	• 3 levels output ➤ VSH1+DCVCOM, DCVCOM, VSL+DCVCOM

- VGH, VGL, VSH1, VSH2, VSL can be connected to external power supply
- Built-in VCOM sensing
- On-chip oscillator
- Programmable output waveform:
 - 40 phases (4 phases/group, 10 groups with repeat function)
 - 1 to 256 times for repeat count
 - Max. 255 frame/phase
- On-chip OTP to store the waveform settings and parameters:
 - 34 sets of waveform setting (WS) including waveform LUT, gate/source voltage and frame rate
 - 34 sets of Temperature Range (TR)
 - VCOM value
 - Waveform version
 - Module identification/User ID
- Embedded OTP to store the initial code setting

- External or internal generated voltage for burning OTP
- Read OTP function and Built-in CRC checking method for waveform setting and temperature range in OTP
- Support Low voltage detect for supply voltage
- Support High voltage ready detect for driving voltage with looping
- Support black/white mono dithering feature
- Support panel break diagnostic
- Support display partial update
- Auto write RAM command for regular pattern
- Internal Temperature Sensor, -25 to 50 degC: accuracy +/- 2degC / 9- bit status
- I2C Single Master Interface to communicate with external temperature sensor
- MCU interface: SPI serial peripheral, Maximum 20MHz for write
- Low current consumption for operation and sleep mode
- Available in COG package

3 ORDERING INFORMATION

Table 3-1 : Ordering Information

Ordering Part Number	Package Form	Remark
SSD1677Z	Gold Bump Die	Bump Face Up On Waffle pack Die thickness: 300um Bump height: 12um
SSD1677Z8	Gold Bump Die	Bump Face Down On Waffle pack Die thickness: 300um Bump height: 12um

4 Block Diagram

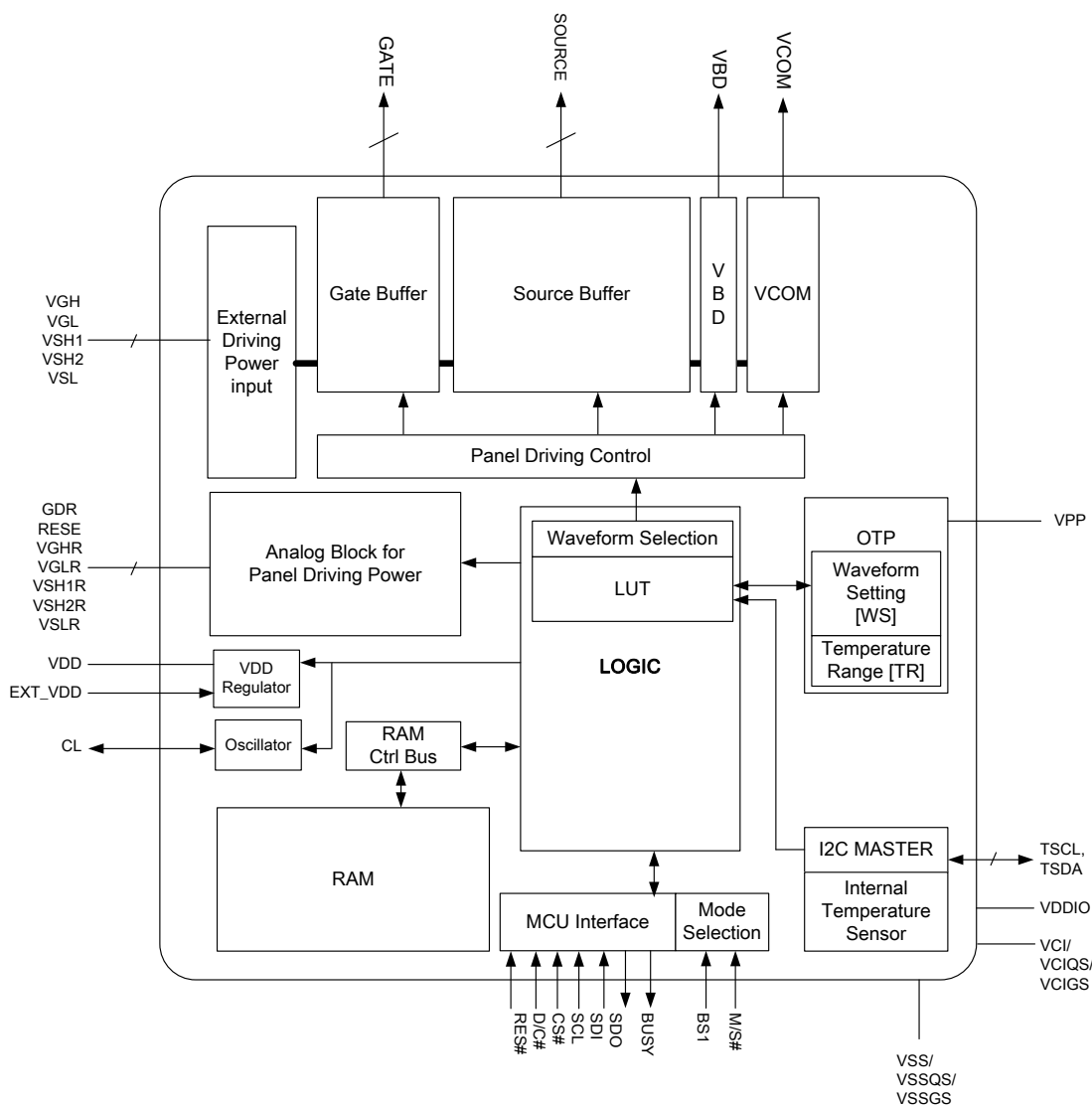


Figure 4-1 : SSD1677 Block Diagram

5 PIN DESCRIPTION

Key:

I = Input
 O =Output
 IO = Bi-directional (input/output)
 P = Power pin
 C = Capacitor Pin
 NC = Not Connected

Table 5-1: Power Supply Pins

Name	Type	Connect to	Function	Description	When not in use
VCI	P	Power Supply	Power Supply	This pin is Power input pin for the chip.	-
VCIGS	P	Power Supply	Power Supply	This pin is Power input pin for the chip. - Connect to VCI in the application circuit.	-
VCIQS	P	Power Supply	Power Supply	This pin is Power input pin for the chip. - Connect to VCI in the application circuit.	-
VDDIO	P	Power Supply	Power for interface logic pins	This pin is Power input pin for the Interface. - Connect to VCI in the application circuit.	-
VDD	P	Capacitor	Regulator output	This pin is Core logic power pin VDD can be regulated internally from VCI. A capacitor should be connected between VDD and VSS under all circumstances.	-
EXTVDD	I	VSS	Regulator bypass	This pin is VDD regulator bypass pin. EXTVDD should be connected to VSS in the application circuit.	-
VSS	P	VSS	GND	This pin is Ground pin	-
VSSGS	P	VSS	GND	This pin is Ground pin. - Connect to VSS in the application circuit.	-
VSSQS	P	VSS	GND	This pin is Ground pin. - Connect to VSS in the application circuit.	-
VPP	P	Power Supply	OTP power	This pin is Power Supply for OTP Programming.	Open

Table 5-2: Interface Logic Pins

Name	Type	Connect to	Function	Description	When not in use						
SCL	I	MPU	Data Bus	This pin is Serial clock pin for interface: Refer to Session 6.1 - MCU Interface.	-						
SDI	I	MPU	Data Bus	This pin is Serial data pin for interface: Refer to Session 6.1 - MCU Interface.	-						
SDO	O				Open						
CS#	I	MPU	Logic Control	This pin is the chip select input connecting to the MCU. Refer to Session 6.1 - MCU Interface.	VDDIO or VSS						
D/C#	I	MPU	Logic Control	This pin is Data/Command control pin connecting to the MCU. Refer to Session 6.1- MCU Interface.	VDDIO or VSS						
RES#	I	MPU	System Reset	This pin is reset signal input. Active Low.	-						
BUSY	O	MPU	Device Busy Signal	This pin is Busy state output pin When Busy is High, the operation of the chip should not be interrupted, and command should not be sent. For example., The chip would put Busy pin High when - Outputting display waveform; or - Programming with OTP - Communicating with digital temperature sensor	Open						
BS1	I	VDDIO/VSS	MCU Interface Mode Selection	This pin is for selecting 3-wire or 4-wire SPI bus. <table><tr><td>BS1</td><td>MCU Interface</td></tr><tr><td>L</td><td>4-wire SPI</td></tr><tr><td>H</td><td>3-wire SPI(9 bits SPI)</td></tr></table>	BS1	MCU Interface	L	4-wire SPI	H	3-wire SPI(9 bits SPI)	-
BS1	MCU Interface										
L	4-wire SPI										
H	3-wire SPI(9 bits SPI)										
M/S#	I	VDDIO	Reserved for Testing	This pin is reserved pin and should be connected to VDDIO.	-						
CL	I/O	NC	Clock signal	This is the clock signal pin. It should be left open in application.	Open						
TSDA	I/O	Temperature sensor SDA	Interface to Digital Temp. Sensor	This pin is I ² C Interface to digital temperature sensor Data pin. External pull up resistor is required when connecting to I ² C slave.	Open						
TSCL	O	Temperature sensor SCL	Interface to Digital Temp. Sensor	This pin is I ² C Interface to digital temperature sensor Clock pin. External pull up resistor is required when connecting to I ² C slave.	Open						

Table 5-3: Analog Pins

Name	Type	Connect to	Function	Description	When not in use
GDR	O	POWER MOSFET Driver Control	VGHR, VGLR Generation	This pin is N-Channel MOSFET gate drive control pin.	-
RESE	I	Booster Control Input		This pin is Current sense input pin for the control Loop.	-
VGHR	C	Stabilizing capacitor		This pin is Positive Gate driving voltage regulation. Connect a stabilizing capacitor between VGHR and VSS in the application circuit.	Open
VGLR	C	Stabilizing capacitor		This pin is Negative Gate driving voltage regulation. Connect a stabilizing capacitor between VGLR and VSS in the application circuit.	Open
VSH1R	C	Stabilizing capacitor	VSH1R, VSH2R, VSLR Generation	This pin is Positive Source driving voltage regulation - VSH1R. Connect a stabilizing capacitor between VSH1R and VSS in the application circuit.	Open
VSH2R	C	Stabilizing capacitor		This pin is Positive Source driving voltage regulation – VSH2R. Connect a stabilizing capacitor between VSH2R and VSS in the application circuit.	Open
VSLR	C	Stabilizing capacitor		This pin is Negative Source driving voltage regulation. Connect a stabilizing capacitor between VSLR and VSS in the application circuit.	Open
VGHR	P	VGHR supply		This pin is Positive Gate driving voltage.	VGHR
VGLR	P	VGLR supply		This pin is Negative Gate driving voltage.	VGLR
VSH1	P	VSH1 supply		This pin is Positive Source driving voltage - VSH1.	VSH1R
VSH2	P	VSH2 supply		This pin is Positive Source driving voltage - VSH2.	VSH2R
VSL	P	VSL supply		This pin is Negative Source driving voltage.	VSLR

Table 5-4: External Power Supply Pins

Name	Type	Connect to	Function	Description	When not in use
VGHR	P	VGHR supply	Analog Pins for External Power Supply	This pin is Positive Gate driving voltage.	VGHR
VGLR	P	VGLR supply		This pin is Negative Gate driving voltage.	VGLR
VSH1R	P	VSH1R supply		This pin is Positive Source driving voltage - VSH1.	VSH1R
VSH2R	P	VSH2R supply		This pin is Positive Source driving voltage - VSH2.	VSH2R
VSLR	P	VSLR supply		This pin is Negative Source driving voltage.	VSLR

Table 5-5: Driver Output Pins

Name	Type	Connect to	Function	Description	When not in use
S [959:0]	O	Panel	Source driving signal	These pins are Source output pin.	Open
G [679:0]	O	Panel	Gate driving signal	These pins are Gate output pin.	Open
VBD	O	Panel	Border driving signal	This pin is Border output pin.	Open
VCOM	C	Panel/ Stabilizing capacitor	VCOM Generation	This pin is VCOM driving voltage Connect a stabilizing capacitor between VCOM and VSS in the application circuit.	-

Table 5-6: Miscellaneous Pins

Name	Type	Connect to	Function	Description	When not in use
RSV	NC	NC	Reserved	This pin is a reserved pin, keep floating	Open
DP[0:33]	I	VSS	Reserved	These pins are reserved pins, connect to VSS.	VSS
TP1,TP2, TP3,TP4, TP5,TP6, TP7,TP8, TP9	NC	NC	Reserved for Testing	Reserved pins. - Keep open. - Don't connect to other NC pins and test pins including TP1,TP2,TP3,TP4,TP5,TP6, TP7,TP8 and TP9	Open
TIN	I	NC	Reserved for Testing	Reserved pins. - Keep open.	Open
TPE	O	NC			Open

6 Functional Block Description

6.1 MCU Interface

6.1.1 MCU Interface selection

SSD1677 can support 4-wire or 3-wire serial peripheral MCU interface, which is pin selectable by BS1 pin. The interface pin assignment for different MCU interfaces is shown in Table 6-1.

Table 6-1: Interface pin assignment for different MCU interfaces

MCU Interface	Pin Name						
	BS1	RES#	CS#	D/C#	SCL	SDI	SDO
4-wire serial peripheral interface (SPI)	L	RES#	CS#	DC#	SCL	SDA	
3-wire serial peripheral interface (SPI) – 9 bits SPI	H	RES#	CS#	L	SCL	SDA	

Note:

- (1) L is connected to V_{SS} and H is connected to V_{DDIO}
- (2) SDI and SDO are connected to be SDA pin for bi-directional data access

6.1.2 MCU Serial Interface (4-wire SPI)

The 4-wire SPI consists of serial clock SCL, serial data input SDI, D/C# and CS#. The control pins status in 4-wire SPI in writing command/data is shown in Table 6-2 and the write procedure in 4-wire SPI is shown in Figure 6-1.

Table 6-2 : Control pins status of 4-wire SPI

Function	SCL pin	SDI pin	D/C# pin	CS# pin
Write command	↑	Command bit	L	L
Write data	↑	Data bit	H	L

Note:

- (1) L is connected to V_{SS} and H is connected to V_{DDIO}
- (2) ↑ stands for rising edge of signal

SDI is shifted into an 8-bit shift register on every rising edge of SCL in the order of D7, D6, ... D0. The level of D/C# should be kept over the whole byte. The data byte in the shift register is written to the Graphic Display Data RAM (RAM)/Data Byte register or command Byte register according to D/C# pin.

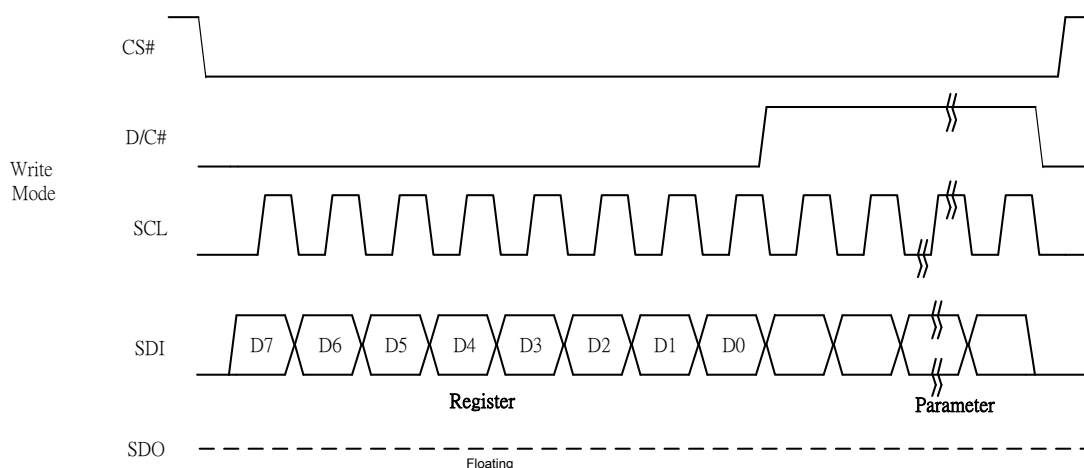


Figure 6-1 : Write procedure in 4-wire SPI mode

In the read operation, after CS# is pulled low, the first byte sent is command byte, D/C# is pulled low. After command byte sent, the following byte(s) read are data byte(s), so D/C# bit is then pulled high. An 8-bit data will be shifted out on every clock falling edge. The serial data output SDO bit shifting sequence is D7, D6, to D0 bit. Figure 6-2 shows the read procedure in 4-wire SPI.

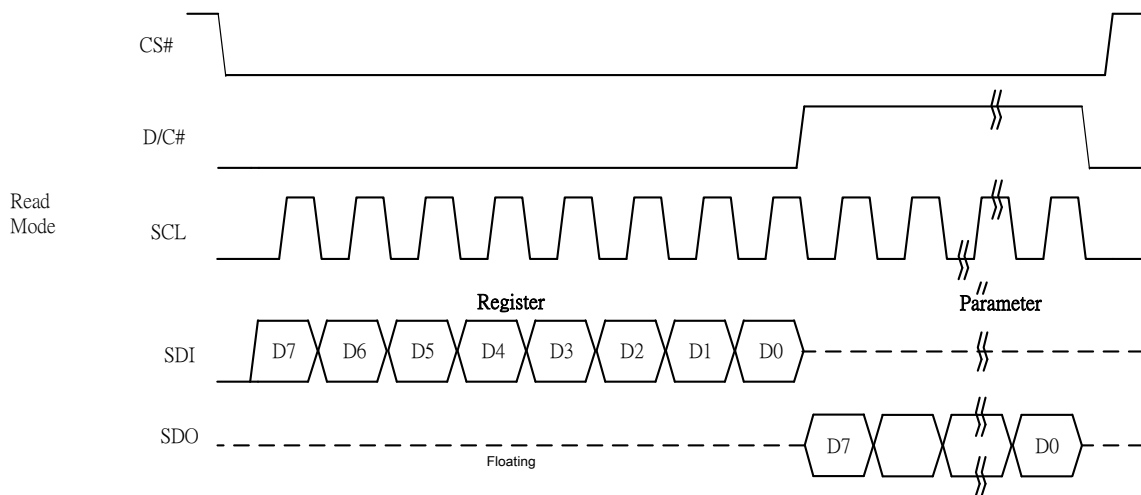


Figure 6-2 : Read procedure in 4-wire SPI mode

6.1.3 MCU Serial Peripheral Interface (3-wire SPI)

The 3-wire SPI consists of serial clock SCL, serial data input SDI, and CS#. The operation is similar to 4-wire SPI while D/C# pin is not used and it must be tied to LOW. The control pins status in 3-wire SPI is shown in Table 6-3.

In the write operation, a 9-bit data will be shifted into the shift register on every clock rising edge. The bit shifting sequence is D/C# bit, D7 bit, D6 bit to D0 bit. The first bit is D/C# bit which determines the following byte is command or data. When D/C# bit is 0, the following byte is command. When D/C# bit is 1, the following byte is data. Table 6-3 shows the write procedure in 3-wire SPI

Table 6-3 : Control pins status of 3-wire SPI

Function	SCL pin	SDI pin	D/C# pin	CS# pin
Write command	↑	Command bit	Tie LOW	L
Write data	↑	Data bit	Tie LOW	L

Note:

- (1) L is connected to V_{SS} and H is connected to V_{DDIO}
- (2) ↑ stands for rising edge of signal

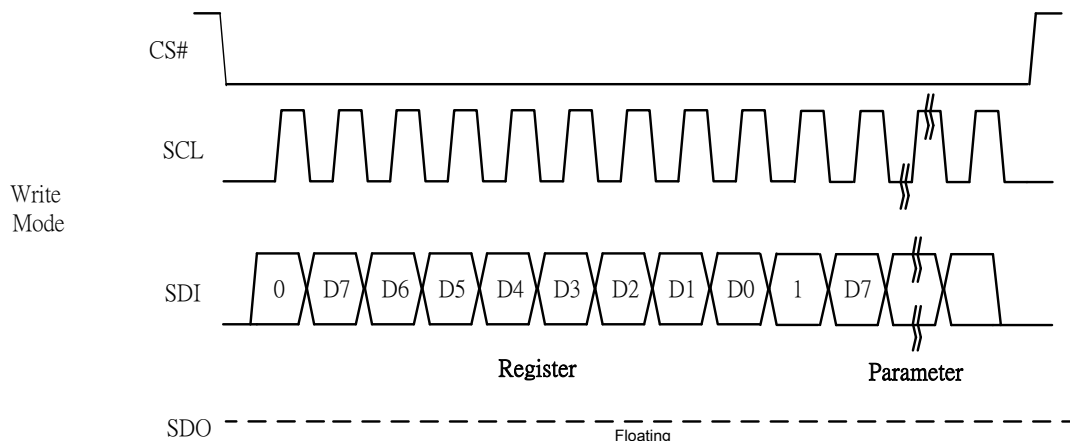


Figure 6-3 : Write procedure in 3-wire SPI

In the read operation, serial data are transferred in the unit of 9 bits. After CS# pull low, the first byte is command byte, the D/C# bit is as 0 and following with the register byte. After command byte send, the following byte(s) are data byte(s), with D/C# bit is 1. After D/C# bit sending from MCU, an 8-bit data will be shifted out on every clock falling edge. The serial data output SDO bit shifting sequence is D7, D6, to D0 bit. Figure 6-4 shows the read procedure in 3-wire SPI.

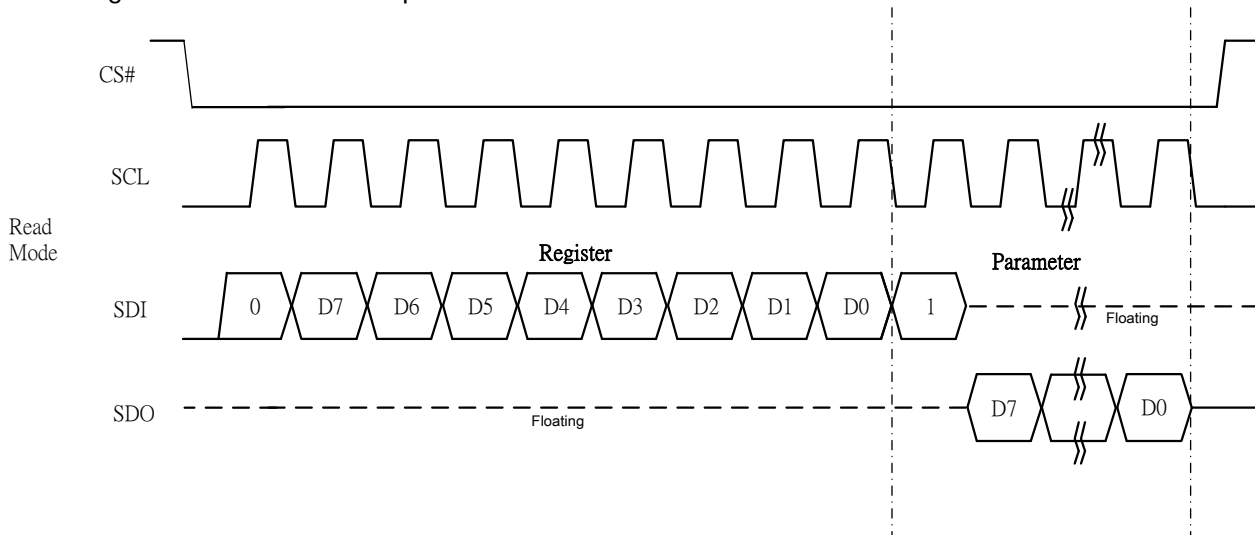


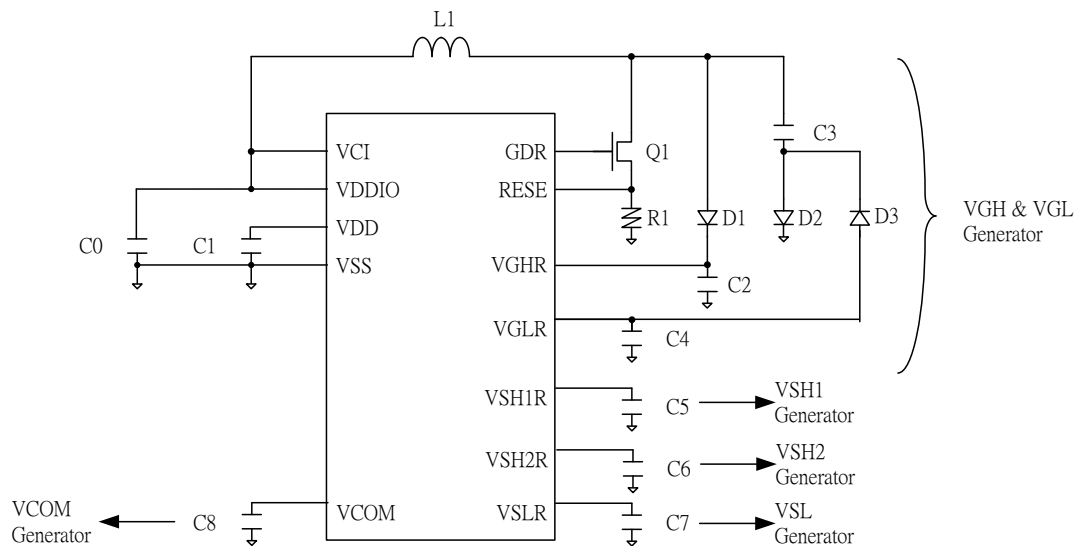
Figure 6-4 : Read procedure in 3-wire SPI mode

6.2 Oscillator

The oscillator module generates the clock reference for waveform timing and analog operations.

6.3 Booster & Regulator

A voltage generation system is included in the driver. It provides all necessary driving voltages required for an AMEPD panel including VGHR, VGLR, VSH1R, VSH2R, VSLR and VCOM. External application circuit is needed to make the on-chip booster & regulator circuit work properly.



With internal power mode, it needs connecting VGHR to VG, VGLR to VGL, VSH1R to VSH1, VSH2R to VSH2 and VSLR to VSL.

SSD1677 support external Gate power [VGH/VGL] and Source power [VSH1/VSH2/VSL]. When external power is connected, VGHR, VGLR, VSH1R, VSH2R and VSL are floating.

6.4 VCOM Sensing

This functional block provides the scheme to sense and set VCOM. The sensed value can also be programmed into OTP.

6.5 RAM

The on-chip display RAM is holding the image data.

1 set of RAM is built for Mono B/W. The RAM size is 960x680 bits.

1 set of RAM is built for Mono Red. The RAM size is 960x680 bits.

Table 6-4 : RAM bit and LUT mapping for 3-color display

Data bit in R RAM	Data bit in B/W RAM	Image Color	LUT
0	0	Black	LUT 0 for driving Black
0	1	White	LUT 1 for driving White
1	0	Red	LUT 2 for driving Red
1	1	Red	LUT 3 = LUT2

Table 6-5 : RAM bit and LUT mapping for black/white display

Data bit in R RAM	Data bit in B/W RAM	Image Color	LUT
0	0	Black	LUT 0 for driving Black
0	1	White	LUT 1 for driving White
1	0	Black	LUT 2 = LUT0
1	1	White	LUT 3 = LUT1

6.6 Programmable Waveform for Gate, Source and VCOM

SSD1677 provides a high flexibility to program the driving waveform. Figure 6-5 illustrates the programmable waveform format for Gate, Source and VCOM.

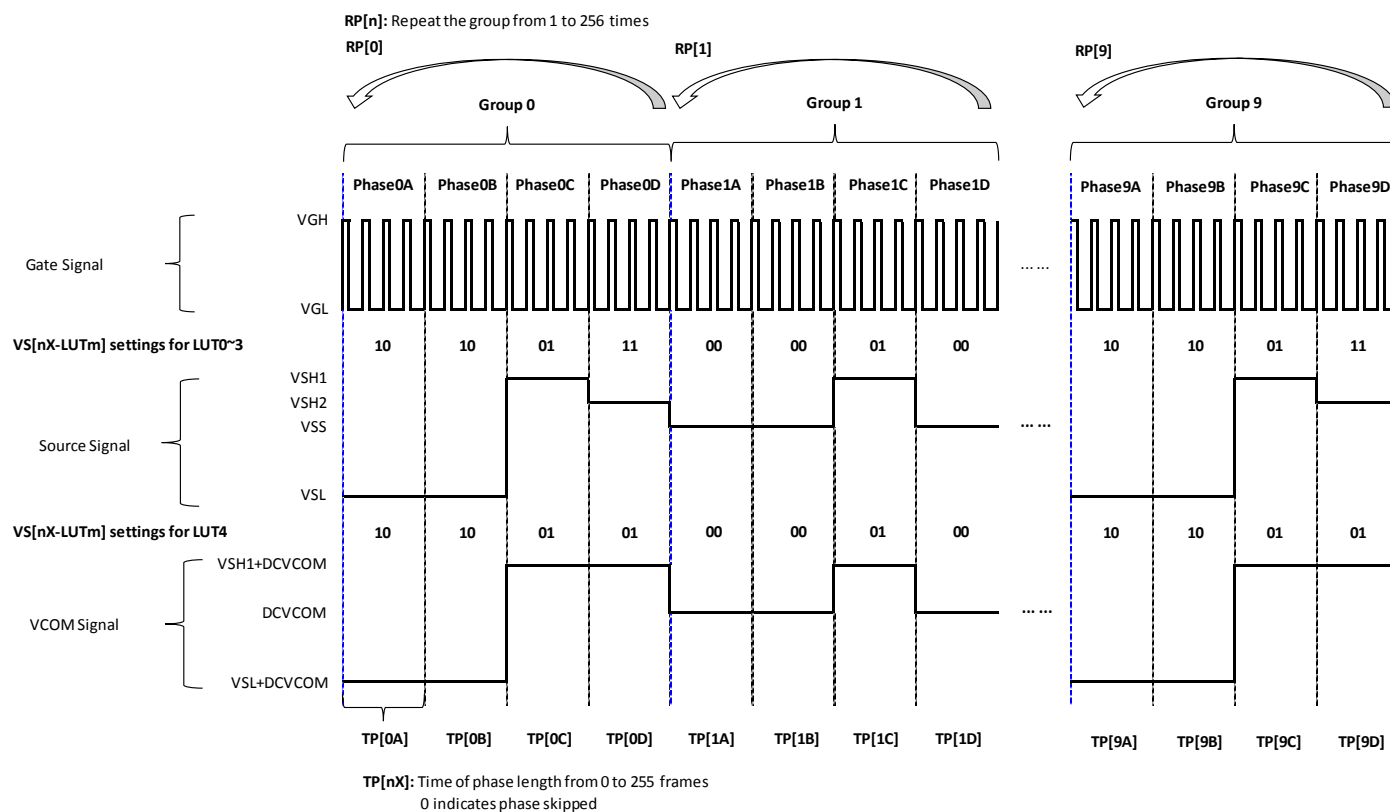


Figure 6-5 : Gate waveform and Programmable Source and VCOM waveform illustration

In the programmable waveform for Source and VCOM, there are 10 groups (Group0 to Group9) and each group has 4 phases (Phase A to Phase D). Totally, there are 40 phases. In addition, in each phase, the phase length (TP[nX]) can be set by number of frame from 0 to 255 frames. Also, each group can be repeated with repeat counting number (RP[n]) from 1 to 256 times. For the voltage, there is four levels for Source voltage (VSS, VSH1, VSH2, VSL) and three levels for VCOM voltage (DCVCOM, VSH1+DCVCOM, VSL+DCVCOM).

The description of each parameter is as follows.

- 1) TP[nX] represents the phase length set by the number of frame.
 - The range of TP[nX] is from 0 to 255.
 - n represents the Group number from 0 to 9; X represents the phase number from A to D.
 - When TP[nX] = 0, the phase is skipped. When TP[nX] = 1, the phase is 1 frame, and so on. The maximum phase length is 255 frame.
- 2) RP[n] represents the repeat counting number for the Group.
 - The range of RP[n] is from 0 to 255.
 - n represents the Group number from 0 to 9.
 - RP[n] = 0 indicates that the repeat times =1, RP[n] = 1 indicates that the repeat times = 2, and so on. The maximum repeat times is 256.
- 3) VS[nX-LUTm] represents Source and VCOM voltage level which is used in each phase. Table 6-6 shows the voltage settings for source voltage and VCOM voltage.
 - n represents the Group number from 0 to 9.
 - m represents the LUT number from 0-4.

Table 6-6 : VS[nX-LUTm] settings for Source voltage and VCOM voltage

VS[nX-LUTm]	Source voltage	VCOM voltage
00	VSS	DCVCOM
01	VSH1	VSH1 + DCVCOM
10	VSL	VSL + DCVCOM
11	VSH2	N/A

6.7 Waveform Lookup Table (LUT)

As described in Section 6.6, parameters TP[nX], RP[n] and VS[nX-LUTm] are used to define the driving waveform. In the SSD1677, there are 112 bytes in the waveform lookup table to store LUT0, LUT1, LUT2, LUT3 and LUT4, gate voltage, source voltage and frame rate. The waveform LUT of a particular temperature range can be loaded from OTP or written by MCU.

- WS byte 0~104, the content of VS [n-XY], TP [n#], RP[n] and frame rate are defined by Register 0x32
- WS byte 105, the content of gate level, is the parameter defined by Register 0x03.
- WS byte 106~108, the content of source level, is the parameter defined by Register 0x04.
- WS byte 109, the content of VCOM level, is the parameter defined by Register 0x2C.
- WS byte 110~111, the contents are reserved.

The SSD1677 waveform LUT is shown in Figure 6-6.

	D7	D6	D5	D4	D3	D2	D1	D0
0	VS[0A-L0]		VS[0B-L0]		VS[0C-L0]		VS[0D-L0]	
1	VS[1A-L0]		VS[1B-L0]		VS[1C-L0]		VS[1D-L0]	
2	VS[2A-L0]		VS[2B-L0]		VS[2C-L0]		VS[2D-L0]	
3	VS[3A-L0]		VS[3B-L0]		VS[3C-L0]		VS[3D-L0]	
4	VS[4A-L0]		VS[4B-L0]		VS[4C-L0]		VS[4D-L0]	
5	VS[5A-L0]		VS[5B-L0]		VS[5C-L0]		VS[5D-L0]	
6	VS[6A-L0]		VS[6B-L0]		VS[6C-L0]		VS[6D-L0]	
7	VS[7A-L0]		VS[7B-L0]		VS[7C-L0]		VS[7D-L0]	
8	VS[8A-L0]		VS[8B-L0]		VS[8C-L0]		VS[8D-L0]	
9	VS[9A-L0]		VS[9B-L0]		VS[9C-L0]		VS[9D-L0]	
10	VS[0A-L1]		VS[0B-L1]		VS[0C-L1]		VS[0D-L1]	
11	VS[1A-L1]		VS[1B-L1]		VS[1C-L1]		VS[1D-L1]	
...								
19	VS[9A-L1]		VS[9B-L1]		VS[9C-L1]		VS[9D-L1]	
20	VS[0A-L2]		VS[0B-L2]		VS[0C-L2]		VS[0D-L2]	
21	VS[1A-L2]		VS[1B-L2]		VS[1C-L2]		VS[1D-L2]	
...								
29	VS[9A-L2]		VS[9B-L2]		VS[9C-L2]		VS[9D-L2]	
...								
...								
40	VS[0A-L4]		VS[0B-L4]		VS[0C-L4]		VS[0D-L4]	
41	VS[1A-L4]		VS[1B-L4]		VS[1C-L4]		VS[1D-L4]	
...								
49	VS[9A-L4]		VS[9B-L4]		VS[9C-L4]		VS[9D-L4]	
50	TP[0A]							
51	TP[0B]							
52	TP[0C]							
53	TP[0D]							
54	RP[0]							
55	TP[1A]							
56	TP[1B]							
57	TP[1C]							
58	TP[1D]							
59	RP[1]							
...	...							
...	...							
95	TP[9A]							
96	TP[9B]							
97	TP[9C]							
98	TP[9D]							
99	RP[9]							
100	5 bytes for frame rate							
101								
102								
103								
104								
105	VGH							
106	VSH1							
107	VSH2							
108	VSL							
109	VCOM							
110	Reserve 1							
111	Reserve 2							

Figure 6-6 : Waveform LUT

6.8 Temperature Sensing

The SSD1677 has internal temperature sensor to detect the environment temperature or can communicate with the external temperature sensor by I2C single master interface or can communicate with the external MCU to get the temperature value through SPI. In the SSD1677, there is a dedicated format for the temperature value so that the driver IC can understand it. The format of temperature value is described in Section 6.8.3.

6.8.1 Internal Temperature Sensor

The internal temperature sensor can be selected by command register. The accuracy of it is $\pm 2^{\circ}\text{C}$ from -25°C to 50°C .

6.8.2 External Temperature Sensor I2C Single Master Interface

The driver IC can communicate with the external temperature sensor through I2C single master interface (TSDA and TSCL). TSDA will be SDA and TSCL will be SCL. TSDA and TSCL are required to connect with external pull-up resistor. Temperature register value of external temperature sensor can be read by command register.

6.8.3 Format of temperature value

The temperature value is defined by 12-bit binary. The rules are shown as below.

- If the Temperature value MSByte bit D11 = 0, then the temperature is positive and value (DegC) = + (Temperature value) / 16
- If the Temperature value MSByte bit D11 = 1, then the temperature is negative and value (DegC) = - (2's complement of Temperature value) / 16

Table 6-7 shows some examples of 12-bit binary temperature value:

Table 6-7 : Example of 12-bit binary temperature settings for temperature ranges

12-bit binary (2's complement)	Hexadecimal Value	TR Value [DegC]
0111 1111 1111	7FF	128
0111 1111 1111	7FF	127.9
0110 0100 0000	640	100
0101 0000 0000	500	80
0100 1011 0000	4B0	75
0011 0010 0000	320	50
0001 1001 0000	190	25
0000 0000 0100	4	0.25
0000 0000 0000	0	0
1111 1111 1100	FFC	-0.25
1110 0111 0000	E70	-25
1100 1001 0000	C90	-55

6.9 Waveform LUT Searching Mechanism

As mentioned in Section 6.7, the SSD1677 OTP can store waveform LUT settings and temperature range. If waveform LUT settings and temperature range are programmed in OTP memory, corresponding waveform LUT can be selected according to the sensed temperature to drive the display. The waveform LUT searching mechanism by driver IC is as follows.

- 1) Read temperature value by command register in the format of 12-bit binary.
- 2) According to read temperature and display mode selection, search LUT in OTP from TR0 to TR33 in sequence. The last match will be selected, then, the corresponding WS will be loaded in the LUT register to drive the display.

Remark: Waveform LUT selection criteria is “Lower temperature bound < Sensed temperature ≤ Upper temperature bound”.

Table 6-8 shows an example for the waveform LUT searching from OTP:

- If the read temperature is 25degC, then, WS4 will be selected.
- If the read temperature is 34degC, then, WS7 will be selected. Although 34degC is also in the temperature range TR6, according to searching mechanism, the last match should be selected. Therefore, WS7 is selected.

Table 6-8 : Example of waveform settings selection based on temperature ranges.

Waveform LUT in OTP	Temperature Range in OTP	TR Lower Limit [Hex]	TR Upper Limit [Hex]	Temperature range in OTP
WS0	TR0	800	050	-128 DegC < Temperature ≤ 5 DegC
WS1	TR1	050	0A0	5 DegC < Temperature ≤ 10DegC
WS2	TR2	0A0	0F0	10 DegC < Temperature ≤ 15DegC
WS3	TR3	0F0	140	15 DegC < Temperature ≤ 20DegC
WS4	TR4	140	190	20 DegC < Temperature ≤ 25DegC
WS5	TR5	190	1E0	25 DegC < Temperature ≤ 30DegC
WS6	TR6	1E0	230	30 DegC < Temperature ≤ 35DegC
WS7	TR7	210	7FF	33 DegC < Temperature ≤ 127.9DegC
Others	Others	000	000	

Precaution:

Please ensure the temperature range covers whole range of application temperatures, display will not be updated if no suitable temperature range matches the sensed temperature.

6.10 One Time Programmable (OTP) Memory

In the SSD1677, there is an embedded OTP memory which is designed to store the waveform settings of different temperature range and some variables/parameters. The OTP memory can store 34 sets of waveform LUT settings (WS), 34 sets of temperature range (TR), VCOM value, display mode selection, waveform version and user ID. Figure 6-7 shows the address mapping of the 34 waveform setting (WS0 to WS33) and temperature range (TR0 to TR33).

	D7	D6	D5	D4	D3	D2	D1	D0
0	WS0							
...								
111								
112	WS1							
...								
223								
224	WS2							
...								
335								
336	WS3							
...								
447								
	...							
3584	WS32							
...								
3695								
3696	WS33							
...								
3807								
3808	TR0							
3809								
3810								
3811	TR1							
3812								
3813								
3814	TR2							
3815								
3816								
3817	TR3							
3818								
3819								
3820	TR4							
3821								
3822								
	...							
3904	TR32							
3905								
3906								
3907	TR33							
3908								
3909								

Figure 6-7 : The Waveform setting mapping in OTP for waveform setting and temperature range

6.10.1 The Format for Temperature Range (TR)

The format of TR Lower limit and Upper limit as shown in Figure 6-8 which temp_L[11:0] is the lower limit and temp_H[11:0] is the upper limit of the temperature range. There has 34sets of TR for waveform LUT searching.

D7	D6	D5	D4	D3	D2	D1	D0
temp_L[7:0]							
temp_H[3:0]				temp_L[11:8]			
temp_H[11:4]							

Figure 6-8 : Format of Temperature Range (TR) in OTP

6.11 VCI Detection

The VCI detection function is used to detect the VCI level when it is lower than Vlow, threshold voltage set by register.

In the SSD1677, there is a command to execute the VCI detection function. When the VCI detection command is issued, the VCI detection will be executed. During the detection period, BUSY output is at high level. BUSY output is at low level when the detection is completed. Then, user can issue the Status Bit Read command to check the status bit for the result of VCI, which 0 is normal, 1 is VCI<Vlow.

6.12 HV Ready Detection

The HV Ready detection function is used for checking if driving voltage is ready before driven the EPD panel.

In the SSD1677, it has the flexibility to set the number of detection and the detection duration for each HV ready detection operation. And, during the detection period, BUSY output is at high level until the operation is completed. After BUSY become to low level, the detection result can be read from Status register.

7 COMMAND TABLE

Table 7-1: Command Table

Command Table																																																							
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description																																											
0	0	01	0	0	0	0	0	0	0	1	Driver Output control	Gate setting A[9:0]= 2A7h [POR], 680 MUX MUX Gate lines setting as (A[9:0] + 1).																																											
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀																																													
0	1		0	0	0	0	0	0	A ₉	A ₈																																													
0	1		0	0	0	0	0	B ₂	B ₁	B ₀		B[2:0] = 000 [POR]. Gate scanning sequence and direction B[2]: GD Selects the 1st output Gate GD=0 [POR], G0 is the 1st gate output channel, gate output sequence is G0,G1, G2, G3, ... GD=1, G1 is the 1st gate output channel, gate output sequence is G1, G0, G3, G2, ... B[1]: SM Change scanning order of gate driver. SM=0 [POR], G0, G1, G2, G3...679 (left and right gate interlaced) SM=1, G0, G2, G4 ...G678, G1, G3, ...G679 B[0]: TB TB = 0, Scan from G0 to G679 TB = 1, Reserved																																											
0	0	03	0	0	0	0	0	0	1	1	Gate Driving voltage Control	Set Gate driving voltage A[4:0] = 00h [POR] VGH setting from 12V to 20V																																											
0	1		0	0	0	A ₄	A ₃	A ₂	A ₁	A ₀		<table><tr><th>A[4:0]</th><th>VGH</th><th>A[4:0]</th><th>VGH</th></tr><tr><td>00h</td><td>20</td><td>10h</td><td>16.5</td></tr><tr><td>07h</td><td>12</td><td>11h</td><td>17</td></tr><tr><td>08h</td><td>12.5</td><td>12h</td><td>17.5</td></tr><tr><td>09h</td><td>13</td><td>13h</td><td>18</td></tr><tr><td>0Ah</td><td>13.5</td><td>14h</td><td>18.5</td></tr><tr><td>0Bh</td><td>14</td><td>15h</td><td>19</td></tr><tr><td>0Ch</td><td>14.5</td><td>16h</td><td>19.5</td></tr><tr><td>0Dh</td><td>15</td><td>17h</td><td>20</td></tr><tr><td>0Eh</td><td>15.5</td><td>Other</td><td>NA</td></tr><tr><td>0Fh</td><td>16</td><td></td><td></td></tr></table>	A[4:0]	VGH	A[4:0]	VGH	00h	20	10h	16.5	07h	12	11h	17	08h	12.5	12h	17.5	09h	13	13h	18	0Ah	13.5	14h	18.5	0Bh	14	15h	19	0Ch	14.5	16h	19.5	0Dh	15	17h	20	0Eh	15.5	Other	NA	0Fh	16	
A[4:0]	VGH	A[4:0]	VGH																																																				
00h	20	10h	16.5																																																				
07h	12	11h	17																																																				
08h	12.5	12h	17.5																																																				
09h	13	13h	18																																																				
0Ah	13.5	14h	18.5																																																				
0Bh	14	15h	19																																																				
0Ch	14.5	16h	19.5																																																				
0Dh	15	17h	20																																																				
0Eh	15.5	Other	NA																																																				
0Fh	16																																																						

Command Table															
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description			
0	0	04	0	0	0	0	0	1	0	0	Source Driving voltage Control	Set Source driving voltage A[7:0] = 41h [POR], VSH1 at 15V B[7:0] = A8h [POR], VSH2 at 5V. C[7:0] = 32h [POR], VSL at -15V			
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀					
0	1		B ₇	B ₆	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀					
0	1		C ₇	C ₆	C ₅	C ₄	C ₃	C ₂	C ₁	C ₀					
B[7] = 1, VSH2 voltage setting from 2.4V to 8.8V			A[7]/B[7] = 0, VSH1/VSH2 voltage setting from 9V to 17V						C[7] = 0, VSL setting from -9V to -17V						
A/B[7:0]		VSH1/VSH2		A/B[7:0]		VSH1/VSH2		A/B[7:0]		VSH1/VSH2		C[7:0]		VSL	
8Eh		2.4		AFh		5.7		23h		9		3Ch		14	
8Fh		2.5		B0h		5.8		24h		9.2		3Dh		14.2	
90h		2.6		B1h		5.9		25h		9.4		3Eh		14.4	
91h		2.7		B2h		6		26h		9.6		3Fh		14.6	
92h		2.8		B3h		6.1		27h		9.8		40h		14.8	
93h		2.9		B4h		6.2		28h		10		41h		15	
94h		3		B5h		6.3		29h		10.2		42h		15.2	
95h		3.1		B6h		6.4		2Ah		10.4		43h		15.4	
96h		3.2		B7h		6.5		2Bh		10.6		44h		15.6	
97h		3.3		B8h		6.6		2Ch		10.8		45h		15.8	
98h		3.4		B9h		6.7		2Dh		11		46h		16	
99h		3.5		BAh		6.8		2Eh		11.2		47h		16.2	
9Ah		3.6		BBh		6.9		2Fh		11.4		48h		16.4	
9Bh		3.7		BCh		7		30h		11.6		49h		16.6	
9Ch		3.8		BDh		7.1		31h		11.8		4Ah		16.8	
9Dh		3.9		BEh		7.2		32h		12		4Bh		17	
9Eh		4		BFh		7.3		33h		12.2		Other		NA	
9Fh		4.1		C0h		7.4		34h		12.4					
A0h		4.2		C1h		7.5		35h		12.6					
A1h		4.3		C2h		7.6		36h		12.8					
A2h		4.4		C3h		7.7		37h		13					
A3h		4.5		C4h		7.8		38h		13.2					
A4h		4.6		C5h		7.9		39h		13.4					
A5h		4.7		C6h		8		3Ah		13.6					
A6h		4.8		C7h		8.1		3Bh		13.8					
A7h		4.9		C8h		8.2									
A8h		5		C9h		8.3									
A9h		5.1		CAh		8.4									
AAh		5.2		CBh		8.5									
ABh		5.3		CCh		8.6									
ACh		5.4		CDh		8.7									
ADh		5.5		CEh		8.8									
AEh		5.6		Other		NA									

Remark:
VSH1> VSH2

Remark:
VSH1> VSH2

Command Table

Command Table																																				
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description																								
0	0	08	0	0	0	0	1	0	0	0	Initial Code Setting OTP Program	Program Initial Code Setting The command required CLKEN=1. Refer to Register 0x22 for detail. BUSY pad will output high during operation.																								
0	0	09	0	0	0	0	1	0	0	1	Write Register for Initial Code Setting	Write Register for Initial Code Setting Selection A[7:0] ~ D[7:0]: Reserved Details refer to Application Notes of Initial Code Setting																								
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀																										
0	1		B ₇	B ₆	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀																										
0	1		C ₇	C ₆	C ₅	C ₄	C ₃	C ₂	C ₁	C ₀																										
0	1		D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀																										
0	0	0A	0	0	0	0	1	0	1	0	Read Register for Initial Code Setting	Read Register for Initial Code Setting																								
0	0	0C	0	0	0	0	1	1	0	0	Booster Soft-start Control	This command is used to control the inrush current for the booster. Two level of strengths can be selected for the booster <table><tr><td></td><td colspan="5">Data bytes</td></tr><tr><td></td><td>A[7:0]</td><td>B[7:0]</td><td>C[7:0]</td><td>D[7:0]</td><td>E[7:0]</td></tr><tr><td>Level 1</td><td>AE</td><td>C7</td><td>C3</td><td>C0</td><td>40</td></tr><tr><td>Level 2</td><td>AE</td><td>C7</td><td>C3</td><td>C0</td><td>80</td></tr></table>		Data bytes						A[7:0]	B[7:0]	C[7:0]	D[7:0]	E[7:0]	Level 1	AE	C7	C3	C0	40	Level 2	AE	C7	C3	C0	80
	Data bytes																																			
	A[7:0]	B[7:0]	C[7:0]	D[7:0]	E[7:0]																															
Level 1	AE	C7	C3	C0	40																															
Level 2	AE	C7	C3	C0	80																															
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀																										
0	1		B ₇	B ₆	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀																										
0	1		C ₇	C ₆	C ₅	C ₄	C ₃	C ₂	C ₁	C ₀																										
0	1		D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀																										
			E ₇	E ₆	E ₅	E ₄	E ₃	E ₂	E ₁	E ₀																										
0	0	10	0	0	0	1	0	0	0	0	Deep Sleep mode	Deep Sleep mode Control: <table><tr><td>A[1:0] :</td><td>Description</td></tr><tr><td>00</td><td>Normal Mode [POR]</td></tr><tr><td>11</td><td>Enter Deep Sleep Mode</td></tr></table> After this command initiated, the chip will enter Deep Sleep Mode, BUSY pad will keep output high. Remark: To Exit Deep Sleep mode, User required to send HWRESET to the driver	A[1:0] :	Description	00	Normal Mode [POR]	11	Enter Deep Sleep Mode																		
A[1:0] :	Description																																			
00	Normal Mode [POR]																																			
11	Enter Deep Sleep Mode																																			
0	1		0	0	0	0	0	0	A ₁	A ₀																										

Command Table												Command	Description
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0			
0	0	11	0	0	0	1	0	0	0	1	Data Entry mode setting	Define data entry sequence A[2:0] = 011 [POR] A [1:0] = ID[1:0] Address automatic increment / decrement setting The setting of incrementing or decrementing of the address counter can be made independently in each upper and lower bit of the address. 00 –Y decrement, X decrement, 01 –Y decrement, X increment, 10 –Y increment, X decrement, 11 –Y increment, X increment [POR] A[2] = AM Set the direction in which the address counter is updated automatically after data are written to the RAM. AM= 0, the address counter is updated in the X direction. [POR] AM = 1, the address counter is updated in the Y direction.	
0	1		0	0	0	0	0	A ₂	A ₁	A ₀			
0	0	12	0	0	0	1	0	0	1	0	SW RESET	It resets the commands and parameters to their SW Reset default values except R10h-Deep Sleep Mode During operation, BUSY pad will output high. Note: RAM are unaffected by this command.	
0	0	14	0	0	0	1	0	1	0	0	HV Ready Detection	HV ready detection A[6:0] = 00h [POR] The command required CLKEN=1 and ANALOGEN=1. Refer to Register 0x22 for detail. After this command initiated, HV Ready detection starts. BUSY pad will output high during detection. The detection result can be read from the Status Bit Read (Command 0x2F).	
0	1		0	A ₆	A ₅	A ₄	0	A ₂	A ₁	A ₀			A[6:4]=n for cool down duration: 10ms x (n+1) A[2:0]=m for number of Cool Down Loop to detect. The max HV ready duration is 10ms x (n+1) x (m) HV ready detection will be trigger after each cool down time. The detection will be completed when HV is ready. For 1 shot HV ready detection, A[7:0] can be set as 00h.

Command Table																										
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description														
0	0	15	0	0	0	1	0	1	0	1	VCI Detection	VCI Detection A[2:0] = 100 [POR] , Detect level at 2.3V A[2:0] : VCI level Detect <table><tr><td>A[2:0]</td><td>VCI level</td></tr><tr><td>011</td><td>2.2V</td></tr><tr><td>100</td><td>2.3V</td></tr><tr><td>101</td><td>2.4V</td></tr><tr><td>110</td><td>2.5V</td></tr><tr><td>111</td><td>2.6V</td></tr><tr><td>Other</td><td>NA</td></tr></table> The command required CLKEN=1 and ANALOGEN=1 Refer to Register 0x22 for detail. After this command initiated, VCI detection starts. BUSY pad will output high during detection. The detection result can be read from the Status Bit Read (Command 0x2F).	A[2:0]	VCI level	011	2.2V	100	2.3V	101	2.4V	110	2.5V	111	2.6V	Other	NA
A[2:0]	VCI level																									
011	2.2V																									
100	2.3V																									
101	2.4V																									
110	2.5V																									
111	2.6V																									
Other	NA																									
0	1		0	0	0	0	0	A ₂	A ₁	A ₀																
0	0	18	0	0	0	1	1	0	0	0	Temperature Sensor Control	Temperature Sensor Selection A[7:0] = 48h [POR], external temperature sensor A[7:0] = 80h Internal temperature sensor														
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀																
0	0	1A	0	0	0	1	1	0	1	0	Temperature Sensor Control (Write to temperature register)	Write to temperature register. A[11:0] = 7FFh [POR]														
0	1		A ₁₁	A ₁₀	A ₉	A ₈	A ₇	A ₆	A ₅	A ₄																
0	1		A ₃	A ₂	A ₁	A ₀	0	0	0	0																
0	0	1B	0	0	0	1	1	0	1	1	Temperature Sensor Control (Read from temperature register)	Read from temperature register.														
1	1		A ₁₁	A ₁₀	A ₉	A ₈	A ₇	A ₆	A ₅	A ₄																
1	1		A ₃	A ₂	A ₁	A ₀	0	0	0	0																

Command Table											Command	Description												
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0														
0	0	1C	0	0	0	1	1	1	0	0	Temperature Sensor Control (Write Command to External temperature sensor)	Write Command to External temperature sensor. A[7:0] = 00h [POR], B[7:0] = 00h [POR], C[7:0] = 00h [POR], A[7:6] <table border="1"><tr><td>A[7:6]</td><td>Select no of byte to be sent</td></tr><tr><td>00</td><td>Address + pointer</td></tr><tr><td>01</td><td>Address + pointer + 1st parameter</td></tr><tr><td>10</td><td>Address + pointer + 1st parameter + 2nd pointer</td></tr><tr><td>11</td><td>Address</td></tr></table> A[5:0] – Pointer Setting B[7:0] – 1 st parameter C[7:0] – 2 nd parameter The command required CLKEN=1. Refer to Register 0x22 for detail. After this command initiated, Write Command to external temperature sensor starts. BUSY pad will output high during operation.	A[7:6]	Select no of byte to be sent	00	Address + pointer	01	Address + pointer + 1st parameter	10	Address + pointer + 1st parameter + 2nd pointer	11	Address		
A[7:6]	Select no of byte to be sent																							
00	Address + pointer																							
01	Address + pointer + 1st parameter																							
10	Address + pointer + 1st parameter + 2nd pointer																							
11	Address																							
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀														
0	1		B ₇	B ₆	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀														
0	1		C ₇	C ₆	C ₅	C ₄	C ₃	C ₂	C ₁	C ₀														
0	0	20	0	0	1	0	0	0	0	0	Master Activation	Activate Display Update Sequence The Display Update Sequence Option is located at R22h. BUSY pad will output high during operation. User should not interrupt this operation to avoid corruption of panel images.												
0	0	21	0	0	1	0	0	0	0	1	Display Update Control 1	RAM content option for Display Update A[7:0] = 00h [POR] A[7:4] Red RAM option <table border="1"><tr><td>0000</td><td>Normal</td></tr><tr><td>0100</td><td>Bypass RAM content as 0</td></tr><tr><td>1000</td><td>Inverse RAM content</td></tr></table> A[3:0] BW RAM option <table border="1"><tr><td>0000</td><td>Normal</td></tr><tr><td>0100</td><td>Bypass RAM content as 0</td></tr><tr><td>1000</td><td>Inverse RAM content</td></tr></table>	0000	Normal	0100	Bypass RAM content as 0	1000	Inverse RAM content	0000	Normal	0100	Bypass RAM content as 0	1000	Inverse RAM content
0000	Normal																							
0100	Bypass RAM content as 0																							
1000	Inverse RAM content																							
0000	Normal																							
0100	Bypass RAM content as 0																							
1000	Inverse RAM content																							
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀														

Command Table											Command	Description	
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0			
0	0	22	0	0	1	0	0	0	1	0	Display Update Control 2	Display Update Sequence Option: Enable the stage for Master Activation A[7:0]= FFh (POR)	
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀			

Command Table												Command	Description
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0			
0	0	24	0	0	1	0	0	1	0	0		Write RAM (Black White) / RAM 0x24	After this command, data entries will be written into the BW RAM until another command is written. Address pointers will advance accordingly For White pixel: Content of Write RAM(BW) = 1 For Black pixel: Content of Write RAM(BW) = 0
0	0	25	0	0	1	0	0	1	0	1		Write RAM (Dithering)	After this command, data entries will be written into the dithering engine.
0	0	26	0	0	1	0	0	1	1	0		Write RAM (RED) / RAM 0x26	After this command, data entries will be written into the RED RAM until another command is written. Address pointers will advance accordingly. For Red pixel: Content of Write RAM(RED) = 1 For non-Red pixel [Black or White]: Content of Write RAM(RED) = 0
0	0	27	0	0	1	0	0	1	1	1		Read RAM	After this command, data read on the MCU bus will fetch data from RAM [According to parameter of Register 41h to select reading RAM(BW) / RAM(RED)], until another command is written. Address pointers will advance accordingly. The 1st byte of data read is dummy data.
0	0	28	0	0	1	0	1	0	0	0		VCOM Sense	Enter VCOM sensing conditions and hold for duration defined in 29h before reading VCOM value. The sensed VCOM voltage is stored in register The command required CLKEN=1 and ANALOGEN=1 Refer to Register 0x22 for detail. BUSY pad will output high during operation.
0	0	29	0	0	1	0	1	0	0	1		VCOM Sense Duration	Stabling time between entering VCOM sensing mode and reading acquired. A[6]=1, Normal Mode A[6]=0, Reserve A[3:0] = 09h, duration = 10s. VCOM sense duration = Setting + 1 Seconds
0	1		0	A ₆	0	0	A ₃	A ₂	A ₁	A ₀			

Command Table															
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description			
0	0	2A	0	0	1	0	1	0	1	0	Program VCOM OTP	Program VCOM register into OTP The command required CLKEN=1. Refer to Register 0x22 for detail. BUSY pad will output high during operation.			
0	0	2B	0	0	1	0	1	0	1	1	Write Register for VCOM Control	This command is used to reduce glitch when ACVCOM toggle. Two data bytes D04h and D63h should be set for this command.			
0	1		0	0	0	0	0	1	0	0					
0	1		0	1	1	0	0	0	1	1					
0	0	2C	0	0	1	0	1	1	0	0	Write VCOM register	Write VCOM register from MCU interface A[7:0] = 00h [POR]			
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀					
												A[7:0]	VCOM	A[7:0]	VCOM
												08h	-0.2	58h	-2.2
												0Ch	-0.3	5Ch	-2.3
												10h	-0.4	60h	-2.4
												14h	-0.5	64h	-2.5
												18h	-0.6	68h	-2.6
												1Ch	-0.7	6Ch	-2.7
												20h	-0.8	70h	-2.8
												24h	-0.9	74h	-2.9
												28h	-1	78h	-3
												2Ch	-1.1	7Ch	-3.1
												30h	-1.2	80h	-3.2
												34h	-1.3	84h	-3.2
												38h	-1.4	88h	-3.4
												3Ch	-1.5	8Ch	-3.5
												40h	-1.6	90h	-3.6
												44h	-1.7	94h	-3.7
												48h	-1.8	98h	-3.8
												4Ch	-1.9	9Ch	-3.9
												50h	-2	A0h	-4
												54h	-2.1	Others	Reserved
0	0	2D	0	0	1	0	1	1	0	1	OTP Register Read for Display Option	Read Register for Display Option: A[7:0]: VCOM OTP Selection (Command 0x37, Byte A) B[7:0]: VCOM Register (Command 0x2C) C[7:0]~G[7:0]: Display Mode (Command 0x37, Byte B to Byte F) [5 bytes] H[7:0]~K[7:0]: Waveform Version (Command 0x37, Byte G to Byte J) [4 bytes]			
1	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀					
1	1		B ₇	B ₆	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀					
1	1		C ₇	C ₆	C ₅	C ₄	C ₃	C ₂	C ₁	C ₀					
1	1		D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀					
1	1		E ₇	E ₆	E ₅	E ₄	E ₃	E ₂	E ₁	E ₀					
1	1		F ₇	F ₆	F ₅	F ₄	F ₃	F ₂	F ₁	F ₀					
1	1		G ₇	G ₆	G ₅	G ₄	G ₃	G ₂	G ₁	G ₀					
1	1		H ₇	H ₆	H ₅	H ₄	H ₃	H ₂	H ₁	H ₀					
1	1		I ₇	I ₆	I ₅	I ₄	I ₃	I ₂	I ₁	I ₀					
1	1		J ₇	J ₆	J ₅	J ₄	J ₃	J ₂	J ₁	J ₀					
1	1		K ₇	K ₆	K ₅	K ₄	K ₃	K ₂	K ₁	K ₀					

Command Table												
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	2E	0	0	1	0	1	1	1	0	User ID Read	Read 10 Byte User ID stored in OTP: A[7:0]~J[7:0]: UserID (R38, Byte A and Byte J) [10 bytes]
1	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀		
1	1		B ₇	B ₆	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀		
1	1		C ₇	C ₆	C ₅	C ₄	C ₃	C ₂	C ₁	C ₀		
1	1		D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀		
1	1		E ₇	E ₆	E ₅	E ₄	E ₃	E ₂	E ₁	E ₀		
1	1		F ₇	F ₆	F ₅	F ₄	F ₃	F ₂	F ₁	F ₀		
1	1		G ₇	G ₆	G ₅	G ₄	G ₃	G ₂	G ₁	G ₀		
1	1		H ₇	H ₆	H ₅	H ₄	H ₃	H ₂	H ₁	H ₀		
1	1		I ₇	I ₆	I ₅	I ₄	I ₃	I ₂	I ₁	I ₀		
1	1		J ₇	J ₆	J ₅	J ₄	J ₃	J ₂	J ₁	J ₀		
0	0	2F	0	0	1	0	1	1	1	1	Status Bit Read	Read IC status Bit [POR 0x01] A[5]: HV Ready Detection flag [POR=0] 0: Ready 1: Not Ready A[4]: VCI Detection flag [POR=0] 0: Normal 1: VCI lower than the Detect level A[3]: [POR=0] A[2]: Busy flag [POR=0] 0: Normal 1: BUSY A[1:0]: Chip ID [POR=01] Remark: A[5] and A[4] status are not valid after RESET, they need to be initiated by command 0x14 and command 0x15 respectively.
1	1		0	0	A ₅	A ₄	0	0	A ₁	A ₀		
0	0	30	0	0	1	1	0	0	0	0	Program WS OTP	Program OTP of Waveform Setting The contents should be written into RAM before sending this command. The command required CLKEN=1. Refer to Register 0x22 for detail. BUSY pad will output high during operation.
0	0	31	0	0	1	1	0	0	0	1	Load WS OTP	Load OTP of Waveform Setting The command required CLKEN=1. Refer to Register 0x22 for detail. BUSY pad will output high during operation.
0	0	32	0	0	1	1	0	0	1	0	Write LUT register	Write LUT register from MCU interface [105 bytes], which contains the content of VS [nX-LUT], TP #[nX], RP#[n].
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀		
0	1		B ₇	B ₆	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀		
0	1		:	:	:	:	:	:	:	:		
0	1		.	..	.	.	.	.	.	.		

Command Table												Command	Description
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0			
0	0	34	0	0	1	1	0	1	0	0		CRC calculation	CRC calculation command BUSY pad will output high during operation.
0	0	35	0	0	1	1	0	1	0	1		CRC Status Read	CRC Status Read A[15:0] is the CRC read out value
1	1		A ₁₅	A ₁₄	A ₁₃	A ₁₂	A ₁₁	A ₁₀	A ₉	A ₈			
1	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀			
0	0	36	0	0	1	1	0	1	1	0		Program OTP selection	Program OTP Selection according to the OTP Selection Control [R37h and R38h] The command required CLKEN=1. Refer to Register 0x22 for detail. BUSY pad will output high during operation.
0	0	37	0	0	1	1	0	1	1	1		Write Register for Display Option	Write Register for Display Option B[7:0] Display Mode for WS[7:0] C[7:0] Display Mode for WS[15:8] D[7:0] Display Mode for WS[23:16] E[7:0] Display Mode for WS[31:24] F[3:0] Display Mode for WS[35:32] 0: Display Mode 1 1: Display Mode 2 F[6]: RAM Ping-Pong for Display Mode 2 1: RAM ping-pong enable 0: RAM ping-pong disable G[7:0]~J[7:0] module ID /waveform version. Remarks: 1) A[7:0]~J[7:0] can be stored in OTP 2) RAM ping-pong function is not support for Display Mode 1
0	1		0	0	0	0	0	0	0	0			
0	1		B ₇	B ₆	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀			
0	1		C ₇	C ₆	C ₅	C ₄	C ₃	C ₂	C ₁	C ₀			
0	1		D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀			
0	1		E ₇	E ₆	E ₅	E ₄	E ₃	E ₂	E ₁	E ₀			
0	1		0	F ₆	0	0	F ₃	F ₂	F ₁	F ₀			
0	1		G ₇	G ₆	G ₅	G ₄	G ₃	G ₂	G ₁	G ₀			
0	1		H ₇	H ₆	H ₅	H ₄	H ₃	H ₂	H ₁	H ₀			
0	1		I ₇	I ₆	I ₅	I ₄	I ₃	I ₂	I ₁	I ₀			
0	1		J ₇	J ₆	J ₅	J ₄	J ₃	J ₂	J ₁	J ₀			
0	0	38	0	0	1	1	1	0	0	0		Write Register for User ID	Write Register for User ID A[7:0]~J[7:0]: UserID [10 bytes] Remarks: A[7:0]~J[7:0] can be stored in OTP
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀			
0	1		B ₇	B ₆	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀			
0	1		C ₇	C ₆	C ₅	C ₄	C ₃	C ₂	C ₁	C ₀			
0	1		D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀			
0	1		E ₇	E ₆	E ₅	E ₄	E ₃	E ₂	E ₁	E ₀			
0	1		F ₇	F ₆	F ₅	F ₄	F ₃	F ₂	F ₁	F ₀			
0	1		G ₇	G ₆	G ₅	G ₄	G ₃	G ₂	G ₁	G ₀			
0	1		H ₇	H ₆	H ₅	H ₄	H ₃	H ₂	H ₁	H ₀			
0	1		I ₇	I ₆	I ₅	I ₄	I ₃	I ₂	I ₁	I ₀			
0	1		J ₇	J ₆	J ₅	J ₄	J ₃	J ₂	J ₁	J ₀			

Command Table												Command	Description																													
0	0	39	0	0	1	1	1	0	0	1	OTP program mode	OTP program mode A[1:0] = 00: Normal Mode [POR] A[1:0] = 11: Internal generated OTP programming voltage Remark: User is required to EXACTLY follow the reference code sequences																														
0	1		0	0	0	0	0	0	A ₁	A ₀																																
0	0	3A	0	0	1	1	1	0	1	0	Reserved	Reserved																														
0	0	3B	0	0	1	1	1	0	1	1	Reserved	Reserved																														
0	0	3C	0	0	1	1	1	1	0	0	Border Waveform Control	Select border waveform for VBD A[7:0] = C0h [POR], set VBD as HiZ. A [7:6] :Select VBD option <table><tr><td>A[7:6]</td><td>Select VBD as</td></tr><tr><td>00</td><td>GS Transition, Defined in A[1:0]</td></tr><tr><td>01</td><td>Fix Level, Defined in A[5:4]</td></tr><tr><td>10</td><td>VCOM</td></tr><tr><td>11[POR]</td><td>HiZ</td></tr></table> A [5:4] Fix Level Setting for VBD <table><tr><td>A[5:4]</td><td>VBD level</td></tr><tr><td>00[POR]</td><td>VSS</td></tr><tr><td>01</td><td>VSH1</td></tr><tr><td>10</td><td>VSL</td></tr><tr><td>11</td><td>VSH2</td></tr></table> A [1:0] GS Transition setting for VBD <table><tr><td>A[1:0]</td><td>VBD Transition</td></tr><tr><td>00[POR]</td><td>LUT0</td></tr><tr><td>01</td><td>LUT1</td></tr><tr><td>10</td><td>LUT2</td></tr><tr><td>11</td><td>LUT3</td></tr></table>	A[7:6]	Select VBD as	00	GS Transition, Defined in A[1:0]	01	Fix Level, Defined in A[5:4]	10	VCOM	11[POR]	HiZ	A[5:4]	VBD level	00[POR]	VSS	01	VSH1	10	VSL	11	VSH2	A[1:0]	VBD Transition	00[POR]	LUT0	01	LUT1	10	LUT2	11	LUT3
A[7:6]	Select VBD as																																									
00	GS Transition, Defined in A[1:0]																																									
01	Fix Level, Defined in A[5:4]																																									
10	VCOM																																									
11[POR]	HiZ																																									
A[5:4]	VBD level																																									
00[POR]	VSS																																									
01	VSH1																																									
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A[1:0]	VBD Transition																																									
00[POR]	LUT0																																									
01	LUT1																																									
10	LUT2																																									
11	LUT3																																									
0	1		A ₇	A ₆	A ₅	A ₄	0	0	A ₁	A ₀																																
0	0	41	0	1	0	0	0	0	0	1	Read RAM Option	Read RAM Option A[0]= 0 [POR] 0: Read RAM corresponding to RAM 0x24 1: Read RAM corresponding to RAM 0x26																														
0	1		0	0	0	0	0	0	0	A ₀																																

Command Table																																																				
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description																																								
0	0	44	0	1	0	0	0	1	0	0	Set RAM X - address Start / End position	Specify the start/end positions of the window address in the X direction by an address unit for RAM A[9:0]: XSA[9:0], XStart, POR = 000h B[9:0]: XEA[9:0], XEnd, POR = 3BFh																																								
0	1		A ₇	A ₈	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀																																										
0	1		-	-	-	-	-	-	A ₉	A ₈																																										
0	1		0	0	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀																																										
0	1		-	-	-	-	-	-	B ₉	B ₈																																										
0	0	45	0	1	0	0	0	1	0	1	Set RAM Y- address Start / End position	Specify the start/end positions of the window address in the Y direction by an address unit for RAM A[9:0]: YSA[9:0], YStart, POR = 000h B[9:0]: YEA[9:0], YEnd, POR = 2A7h																																								
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀																																										
0	1		-	-	-	-	-	-	A ₉	A ₈																																										
0	1		B ₇	B ₆	B ₅	B ₄	B ₃	B ₂	B ₁	B ₀																																										
0	1		-	-	-	-	-	-	B ₉	B ₈																																										
0	0	46	0	1	0	0	0	1	1	0	Auto Write RED RAM for Regular Pattern	Auto Write RED RAM for Regular Pattern A[7:0] = 00h [POR] A[7]: The 1st step value, POR = 0 A[6:4]: Step Height, POR= 000 Step of alter RAM in Y-direction according to Gate <table><tr><th>A[6:4]</th><th>Height</th><th>A[6:4]</th><th>Height</th></tr><tr><td>000</td><td>8</td><td>100</td><td>128</td></tr><tr><td>001</td><td>16</td><td>101</td><td>256</td></tr><tr><td>010</td><td>32</td><td>110</td><td>512</td></tr><tr><td>011</td><td>64</td><td>111</td><td>680</td></tr></table> A[2:0]: Step Width, POR= 000 Step of alter RAM in X-direction according to Source <table><tr><th>A[2:0]</th><th>Width</th><th>A[2:0]</th><th>Width</th></tr><tr><td>000</td><td>8</td><td>100</td><td>128</td></tr><tr><td>001</td><td>16</td><td>101</td><td>256</td></tr><tr><td>010</td><td>32</td><td>110</td><td>512</td></tr><tr><td>011</td><td>64</td><td>111</td><td>960</td></tr></table> BUSY pad will output high during operation.	A[6:4]	Height	A[6:4]	Height	000	8	100	128	001	16	101	256	010	32	110	512	011	64	111	680	A[2:0]	Width	A[2:0]	Width	000	8	100	128	001	16	101	256	010	32	110	512	011	64	111	960
A[6:4]	Height	A[6:4]	Height																																																	
000	8	100	128																																																	
001	16	101	256																																																	
010	32	110	512																																																	
011	64	111	680																																																	
A[2:0]	Width	A[2:0]	Width																																																	
000	8	100	128																																																	
001	16	101	256																																																	
010	32	110	512																																																	
011	64	111	960																																																	
0	1		A ₇	A ₆	A ₅	A ₄	0	A ₂	A ₁	A ₀																																										

Command Table												Command	Description																																								
0	0	47	0	1	0	0	0	1	1	1		Auto Write B/W RAM for Regular Pattern	Auto Write B/W RAM for Regular Pattern A[7:0] = 00h [POR] A[7]: The 1st step value, POR = 0 A[6:4]: Step Hieght, POR= 000 Step of alter RAM in Y-direction according to Gate <table><tr><td>A[6:4]</td><td>Height</td><td>A[6:4]</td><td>Height</td></tr><tr><td>000</td><td>8</td><td>100</td><td>128</td></tr><tr><td>001</td><td>16</td><td>101</td><td>256</td></tr><tr><td>010</td><td>32</td><td>110</td><td>512</td></tr><tr><td>011</td><td>64</td><td>111</td><td>680</td></tr></table> A[2:0]: Step Width, POR= 000 Step of alter RAM in X-direction according to Source <table><tr><td>A[2:0]</td><td>Width</td><td>A[2:0]</td><td>Width</td></tr><tr><td>000</td><td>8</td><td>100</td><td>128</td></tr><tr><td>001</td><td>16</td><td>101</td><td>256</td></tr><tr><td>010</td><td>32</td><td>110</td><td>512</td></tr><tr><td>011</td><td>64</td><td>111</td><td>960</td></tr></table> During operation, BUSY pad will output high.	A[6:4]	Height	A[6:4]	Height	000	8	100	128	001	16	101	256	010	32	110	512	011	64	111	680	A[2:0]	Width	A[2:0]	Width	000	8	100	128	001	16	101	256	010	32	110	512	011	64	111	960
A[6:4]	Height	A[6:4]	Height																																																		
000	8	100	128																																																		
001	16	101	256																																																		
010	32	110	512																																																		
011	64	111	680																																																		
A[2:0]	Width	A[2:0]	Width																																																		
000	8	100	128																																																		
001	16	101	256																																																		
010	32	110	512																																																		
011	64	111	960																																																		
0	0	4D	0	1	0	0	1	1	0	1		Dithering engine Start/Stop	This command is used for start and stop dithering function, start commands should be sent before Command 0x25 and stop commands should be sent after the data bytes of command 0x25 <table><tr><td></td><td colspan="4">Data byte</td></tr><tr><td></td><td>A[7:0]</td><td>B[7:0]</td><td>C[7:0]</td><td>D[7:0]</td></tr><tr><td>Start Sierra Lite</td><td>80</td><td>00</td><td>78</td><td>00</td></tr><tr><td>Start Floyd-Steinberg</td><td>83</td><td>00</td><td>78</td><td>00</td></tr><tr><td>Stop dithering</td><td>00</td><td>00</td><td>78</td><td>00</td></tr></table>		Data byte					A[7:0]	B[7:0]	C[7:0]	D[7:0]	Start Sierra Lite	80	00	78	00	Start Floyd-Steinberg	83	00	78	00	Stop dithering	00	00	78	00															
	Data byte																																																				
	A[7:0]	B[7:0]	C[7:0]	D[7:0]																																																	
Start Sierra Lite	80	00	78	00																																																	
Start Floyd-Steinberg	83	00	78	00																																																	
Stop dithering	00	00	78	00																																																	
0	0	4E	0	1	0	0	1	1	1	0		Set RAM X address counter	Make initial settings for the RAM X address in the address counter (AC) A[9:0]: 000h [POR].																																								
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀																																											
0	1		0	0	0	0	0	0	A ₉	A ₈																																											
0	0	4F	0	1	0	0	1	1	1	1		Set RAM Y address counter	Make initial settings for the RAM Y address in the address counter (AC) A[9:0]: 000h [POR].																																								
0	1		A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀																																											
0	1		0	0	0	0	0	0	A ₉	A ₈																																											
0	0	7F	0	1	1	1	1	1	1	1		NOP	This command is an empty command; it does not have any effect on the display module. However, it can be used to terminate Frame Memory Write or Read Commands.																																								

8 COMMAND DESCRIPTION

8.1 Driver Output Control (01h)

This triple byte command has multiple configurations and each bit setting is described as follows:

Table 8-1 : POR settings for Driver Output Control (Command 0x01)

R/W	DC	D7	D6	D5	D4	D3	D2	D1	D0
W	1	MUX7	MUX6	MUX5	MUX4	MUX3	MUX2	MUX1	MUX0
POR		1	0	1	0	0	1	1	1
W	1							MUX9	MUX8
POR								1	0
W	1						GD	SM	TB
POR							0	0	0

MUX[9:0]: Specify number of lines for the driver: MUX[9:0] + 1. Multiplex ratio (MUX ratio) from 300 MUX to 680MUX.

TB: This bit is set at "0" for scanning from gate 0. Option TB = 1 is reserved.

SM: Change scanning order of gate driver.

When SM is set to 0, left and right interlaced is performed.

When SM is set to 1, no splitting odd / even of the GATE signal is performed,

Output pin assignment sequence is shown as below (for 680 MUX ratio):

GD: Selects the 1st output Gate

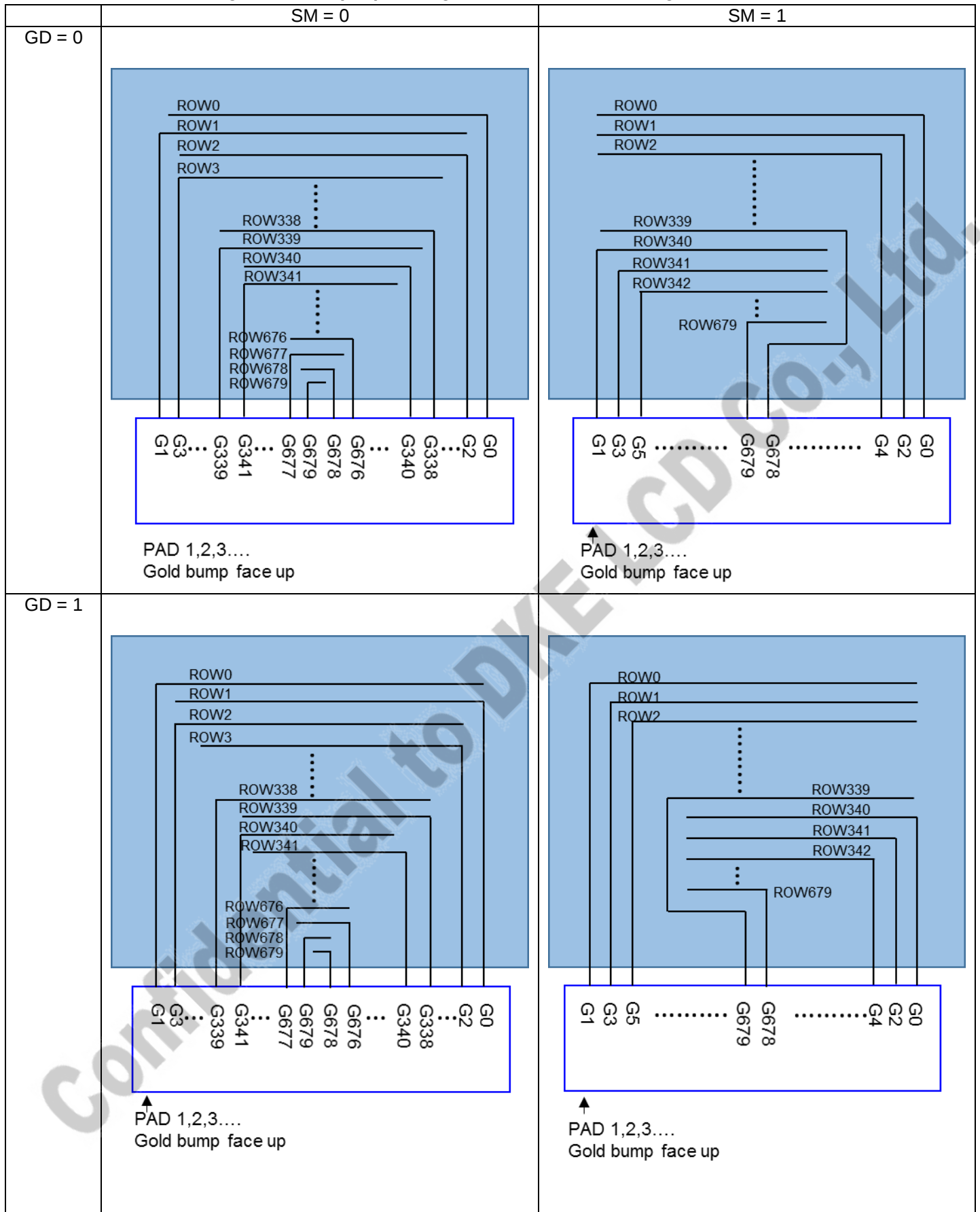
This bit is made to match the GATE layout connection on the panel. It defines the first scanning line.

Table 8-2 and Figure 8-1 illustrate in details about GD and SM.

Table 8-2 : Output pin assignment sequence of SM and GD settings

	SM=0 GD=0	SM=0 GD=1	SM=1 GD=0	SM=1 GD=1
Driver				
G0	ROW0	ROW1	ROW0	ROW340
G1	ROW1	ROW0	ROW340	ROW0
G2	ROW2	ROW3	ROW1	ROW341
G3	ROW3	ROW2	ROW341	ROW1
⋮	⋮	⋮	⋮	⋮
G338	ROW338	ROW339	ROW170	ROW510
G339	ROW339	ROW338	ROW510	ROW170
G340	ROW340	ROW341	ROW171	ROW511
G341	ROW341	ROW340	ROW511	ROW171
⋮	⋮	⋮	⋮	⋮
G676	ROW676	ROW677	ROW338	ROW678
G677	ROW677	ROW676	ROW678	ROW338
G678	ROW678	ROW679	ROW339	ROW679
G679	ROW679	ROW678	ROW679	ROW339

Figure 8-1: Output pin assignment on different setting of GD and SM



8.2 Data Entry Mode Setting (11h)

This command has multiple configurations and each bit setting is described as follows:

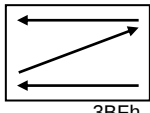
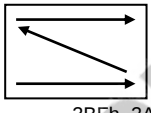
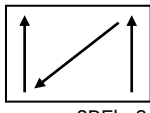
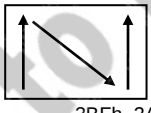
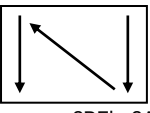
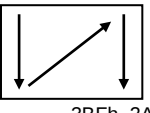
Table 8-3 : POR settings for Data Entry Mode Setting (Command 0x11)

R/W	DC	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
W	1						AM	ID1	ID0
POR		0	0	0	0	0	0	1	1

ID[1:0]: The address counter is automatically incremented by 1, after data is written to the RAM when ID[1:0] = "01". The address counter is automatically decremented by 1, after data is written to the RAM when ID[1:0] = "00". The setting of incrementing or decrementing of the address counter can be made independently in each upper and lower bit of the address. The direction of the address when data is written to the RAM is set by AM bits.

AM: Set the direction in which the address counter is updated automatically after data are written to the RAM. When AM = "0", the address counter is updated in the X direction. When AM = "1", the address counter is updated in the Y direction. When window addresses are selected, data are written to the RAM area specified by the window addresses in the manner specified with ID[1:0] and AM bits.

Table 8-4 : Address counter directions of ID and AM settings (Command 0x11)

	ID [1:0]="00" X: decrement Y: decrement	ID [1:0]="01" X: increment Y: decrement	ID [1:0]="10" X: decrement Y: increment	ID [1:0]="11" X: increment Y: increment
AM="0" X-mode	00,00h  3BFh, 2A7h	00,00h  3BFh, 2A7h	00,00h  3BFh, 2A7h	00,00h  3BFh, 2A7h
AM="1" Y-mode	00,00h  3BFh, 2A7h	00,00h  3BFh, 2A7h	00,00h  3BFh, 2A7h	00,00h  3BFh, 2A7h

8.3 Set RAM X - Address Start / End Position (44h)

This command is used to set the start/ end position of the window address in X-direction.

Table 8-5 : POR settings for Set RAM X - Address Start / End Position (Command 0x44)

R/W	DC	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
W	1	XSA7	XSA6	XSA5	XSA4	XSA3	XSA2	XSA1	XSA0
POR		0	0	0	0	0	0	0	0
W	1	-	-	-	-	-	-	XSA9	XSA8
POR		-	-	-	-	-	-	0	0
W	1	XEA7	XEA6	XEA5	XEA4	XEA3	XEA2	XEA1	XEA0
POR		1	0	1	1	1	1	1	1
W	1	-	-	-	-	-	-	XEA9	XEA8
POR		-	-	-	-	-	-	1	1

XSA[9:0]/XEA[9:0]: Specify the start/end positions of the window address in the X direction by an address unit. Data is written to the RAM within the area determined by the addresses specified by XSA [9:0] and XEA [9:0]. These addresses must be set before the RAM write.

It allows on $XEA [9:0] \leq XSA [9:0]$. The settings follow the condition on $00h \leq XSA [9:0]$, $XEA [9:0] \leq 3BFh$.

The window is followed by the control setting of Data Entry Setting (R11h)

8.4 Set RAM Y - Address Start / End Position (45h)

This command is used to set the start/ end position of the window address in Y-direction.

Table 8-6 : POR settings for Set RAM Y - Address Start / End Position (Command 0x45)

R/W	DC	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
W	1	YSA7	YSA6	YSA5	YSA4	YSA3	YSA2	YSA1	YSA0
POR		0	0	0	0	0	0	0	0
W	1	0	0	0	0	0	0	YSA9	YSA8
POR		0	0	0	0	0	0	0	0
W	1	YEA7	YEA6	YEA5	YEA4	YEA3	YEA2	YEA1	YEA0
POR		1	0	1	0	0	1	1	1
W	1	0	0	0	0	0	0	YEA9	YEA8
POR		0	0	0	0	0	0	1	0

YSA[9:0]/YEA[9:0]: Specify the start/end positions of the window address in the Y direction by an address unit. Data is written to the RAM within the area determined by the addresses specified by YSA [9:0] and YEA [9:0]. These addresses must be set before the RAM write.

It allows $YEA [9:0] \leq YSA [9:0]$. The settings follow the condition on $00h \leq YSA [9:0]$, $YEA [9:0] \leq 2A7h$.

The window is followed by the control setting of Data Entry Setting (R11h)

8.5 Set RAM Address Counter (4Eh-4Fh)

These commands are used to set the start position of RAM address counter.

Table 8-7 : POR settings for Set RAM Address Counter (Command 0x4E~4F)

Reg#	R/W	DC	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
4Eh	W	1	XAD7	XAD6	XAD5	XAD4	XAD3	XAD2	XAD1	XAD0
	POR		0	0	0	0	0	0	0	0
	W	1	-	-	-	-	-	-	XAD9	XAD8
	POR		-	-	-	-	-	-	0	0
4Fh	W	1	YAD7	YAD6	YAD5	YAD4	YAD3	YAD2	YAD1	YAD0
	POR		0	0	0	0	0	0	0	0
	W	1	-	-	-	-	-	-	YAD9	YAD8
	POR		-	-	-	-	-	-	0	0

XAD[9:0]: Make initial settings for the RAM X address in the address counter (AC).

YAD[9:0]: Make initial settings for the RAM Y address in the address counter (AC).

After RAM data is written, the address counter is automatically updated according to the settings with AM, ID bits and setting for a new RAM address is not required in the address counter. Therefore, data is written consecutively without setting an address. The address counter is not automatically updated when data is read out from the RAM. RAM address setting cannot be made during the standby mode. The address setting should be made within the area designated with window addresses which is controlled by the Data Entry Setting (R11h) {AM, ID[1:0]} ; RAM Address XStart / XEnd Position (R44h) and RAM Address Ystart /Yend Position (R45h). Otherwise undesirable image will be displayed on the Panel.

9 Operation Flow and Code Sequence

9.1 General operation flow to drive display panel

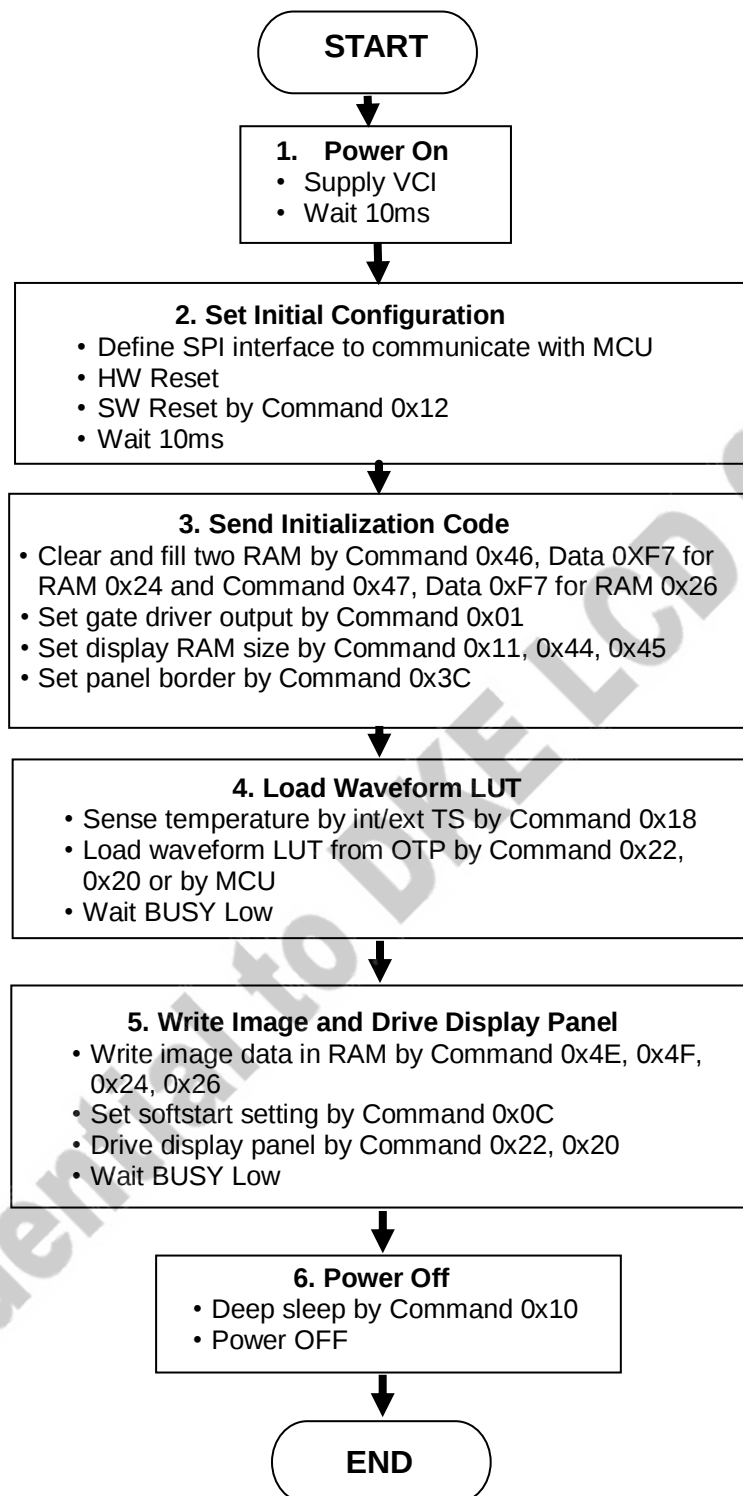


Figure 9-1: Operation flow to drive display panel

10 Absolute Maximum Rating

Table 10-1 : Maximum Ratings

Symbol	Parameter	Rating	Unit
V _{CI}	Logic supply voltage	-0.5 to +4.0	V
V _{IN}	Logic Input voltage	-0.5 to V _{DDIO} +0.5	V
V _{OUT}	Logic Output voltage	-0.5 to V _{DDIO} +0.5	V
T _{OPR}	Operation temperature range	-25 to 85	°C
T _{STG}	Storage temperature range	-65 to +150	°C

Maximum ratings are those values beyond which damages to the device may occur. Functional operation should be restricted to the limits in the Electrical Characteristics tables or Pin Description section

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high impedance circuit. For proper operation it is recommended that V_{CI} be constrained to the range V_{SS} < V_{CI}. Reliability of operation is enhanced if unused input is connected to an appropriate logic voltage level (e.g., either V_{SS} or V_{DDIO}). Unused outputs must be left open. This device may be light sensitive. Caution should be taken to avoid exposure of this device to any light source during normal operation. This device is not radiation protected.

11 Electrical Characteristics

The following specifications apply for: V_{SS}=0V, V_{CI}=3.0V, V_{DD}=1.8V, T_{OPR}=25°C.

Table 11-1: DC Characteristics

Symbol	Parameter	Applicable pin	Test Condition	Min.	Typ.	Max.	Unit
V _{CI}	V _{CI} operation voltage	V _{CI}		2.2	3.0	3.3	V
V _{DD}	V _{DD} operation voltage	V _{DD}		1.7	1.8	1.9	V
V _{COM_DC}	V _{COM_DC} output voltage	V _{COM}		-4.0		-0.1	V
dV _{COM_DC}	V _{COM_DC} output voltage deviation	V _{COM}		-100		100	mV
V _{COM_AC}	V _{COM_AC} output voltage	V _{COM}		V _{SL} + V _{COM_DC}	V _{COM_DC}	V _{SH1} + V _{COM_DC}	V
V _{GATE}	Gate output voltage	G0~G679		-20		+20	V
V _{GATE(p-p)}	Gate output peak to peak voltage	G0~G679				40	V
V _{SH1R}	Positive Source output voltage	VSH1R		+9	+15	+17	V
dV _{SH1R}	VSH1R output voltage deviation	VSH1R		-200		200	mV
V _{SH2R}	Positive Source output voltage	VSH2R		+2.4	+5	+17	V
dV _{SH2R}	VSH2R output voltage deviation	VSH2R	2.4V to 8.8V	-100		100	mV
			8.8V to 17V	-200		200	mV
V _{SLR}	Negative Source output voltage	VSLR		-17	-15	-9	V
dV _{SLR}	VSLR output voltage deviation	VSLR		-200		200	mV
V _{IH}	High level input voltage	SDA, SCL, CS#, D/C#, RES#, BS1, M/S#, EXTVD, CL		0.8V _{DDIO}			V
V _{IL}	Low level input voltage					0.2V _{DDIO}	V
V _{OH}	High level output voltage	SDA, BUSY, CL	I _{OH} = -100uA	0.9V _{DDIO}			V
V _{OL}	Low level output voltage		I _{OL} = 100uA			0.1V _{DDIO}	V

Symbol	Parameter	Applicable pin	Test Condition	Min.	Typ.	Max.	Unit
V _{PP}	OTP Program voltage	V _{PP}		7.25	7.5	7.75	V
I _{slp_VCI}	Sleep mode current	VCI	- DC/DC off - No clock - No output load - MCU interface access - RAM data access		25	40	uA
I _{dslp_VCI}	Deep sleep mode current	VCI	- DC/DC off - No clock - No output load - No MCU interface access - Cannot retain RAM data		1	5	uA
I _{opr_VCI}	Operating Mode current	VCI	VCI=3.0V		2.0		mA
V _{GH}	Operating Mode Output Voltage	VGH	Enable Clock and Analog by Master Activation Command VGH=20V VGL=-VGH VSH1=15V VSH2=5V VSL=-15V VCOM = -2V No waveform transitions. No loading. No RAM read/write No OTP read /write	19.5	20	20.5	V
V _{SH1}		VSH1		14.8	15	15.2	V
V _{SH2}		VSH2		4.9	5	5.1	V
V _{SL}		VSL		-15.2	-15	-14.8	V
V _{COM}		VCOM		-2.2	-2	-1.8	V

Table 11-2: Regulators Characteristics

Symbol	Parameter	Test Condition	Applicable pin	Min.	Typ.	Max.	Unit
I _{VGH}	VGH current	VGH = 20V	VGH			1000	uA
I _{VGL}	VGL current	VGL = -VGH	VGL			1000	uA
I _{VSH}	VSH1 current	VSH1 = +15V	VSH1			2000	uA
I _{VSH1}	VSH2 current	VSH2 = +5V	VSH2			2000	uA
I _{VSL}	VSL current	VSL = -15V	VSL			2000	uA
I _{VCOM}	VCOM current	VCOM = -2V	VCOM			2000	uA

12 AC Characteristics

12.1 Serial Peripheral Interface

The following specifications apply for: VDDIO - VSS = 2.2V to 3.7V, T_{OPR} = 25°C, CL=30pF

Table 12-1 : Serial Peripheral Interface Timing Characteristics

Write mode

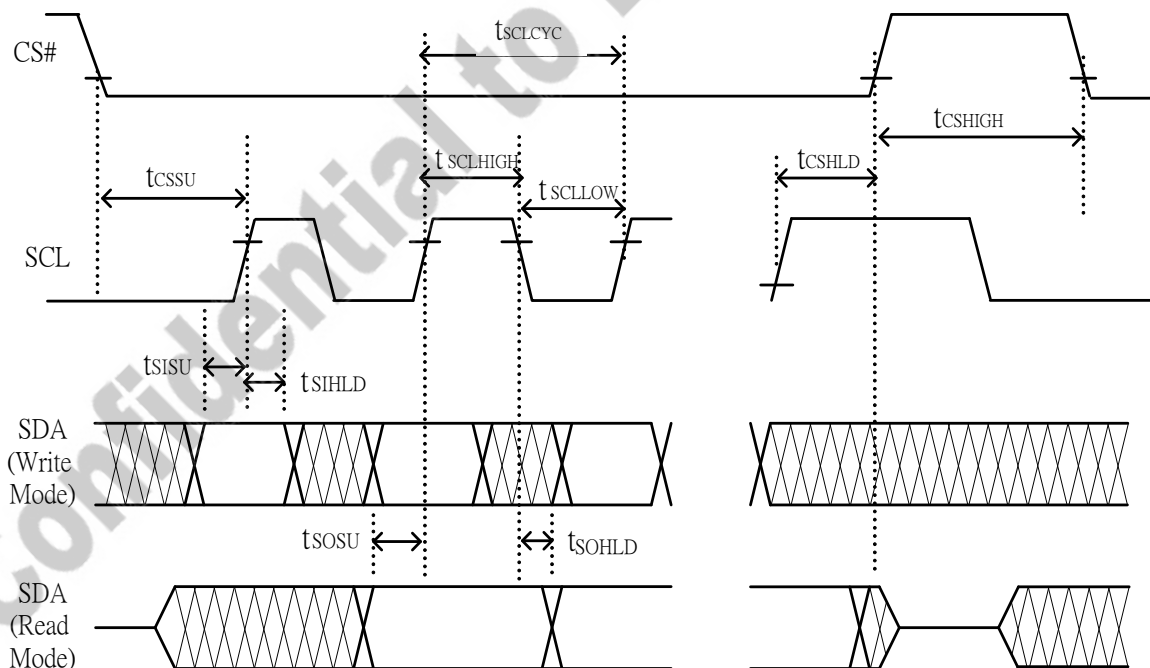
Symbol	Parameter	Min	Typ	Max	Unit
f _{SCL}	SCL frequency (Write Mode)			20	MHz
t _{CSSU}	Time CS# has to be low before the first rising edge of SCLK	20			ns
t _{CSHLD}	Time CS# has to remain low after the last falling edge of SCLK	20			ns
t _{CSHIGH}	Time CS# has to remain high between two transfers	100			ns
t _{SCLCYC}	SCL cycle time	50			ns
t _{SCLHIGH}	Part of the clock period where SCL has to remain high	25			ns
t _{SCLLOW}	Part of the clock period where SCL has to remain low	25			ns
t _{SISU}	Time SI (SDA Write Mode) has to be stable before the next rising edge of SCL	10			ns
t _{SIHLD}	Time SI (SDA Write Mode) has to remain stable after the rising edge of SCL	40			ns

Read mode

Symbol	Parameter	Min	Typ	Max	Unit
f _{SCL}	SCL frequency (Read Mode)			2.5	MHz
t _{CSSU}	Time CS# has to be low before the first rising edge of SCLK	100			ns
t _{CSHLD}	Time CS# has to remain low after the last falling edge of SCLK	50			ns
t _{CSHIGH}	Time CS# has to remain high between two transfers	250			ns
t _{SCLHIGH}	Part of the clock period where SCL has to remain high	180			ns
t _{SCLLOW}	Part of the clock period where SCL has to remain low	180			ns
t _{SOSU}	Time SO (SDA Read Mode) will be stable before the next rising edge of SCL		50		ns
t _{SOHLD}	Time SO (SDA Read Mode) will remain stable after the falling edge of SCL		0		ns

Note: All timings are based on 20% to 80% of VDDIO-VSS

Figure 12-1: SPI timing diagram



13 Application Circuit

Figure 13-1: Schematic of SSD1677 application circuit

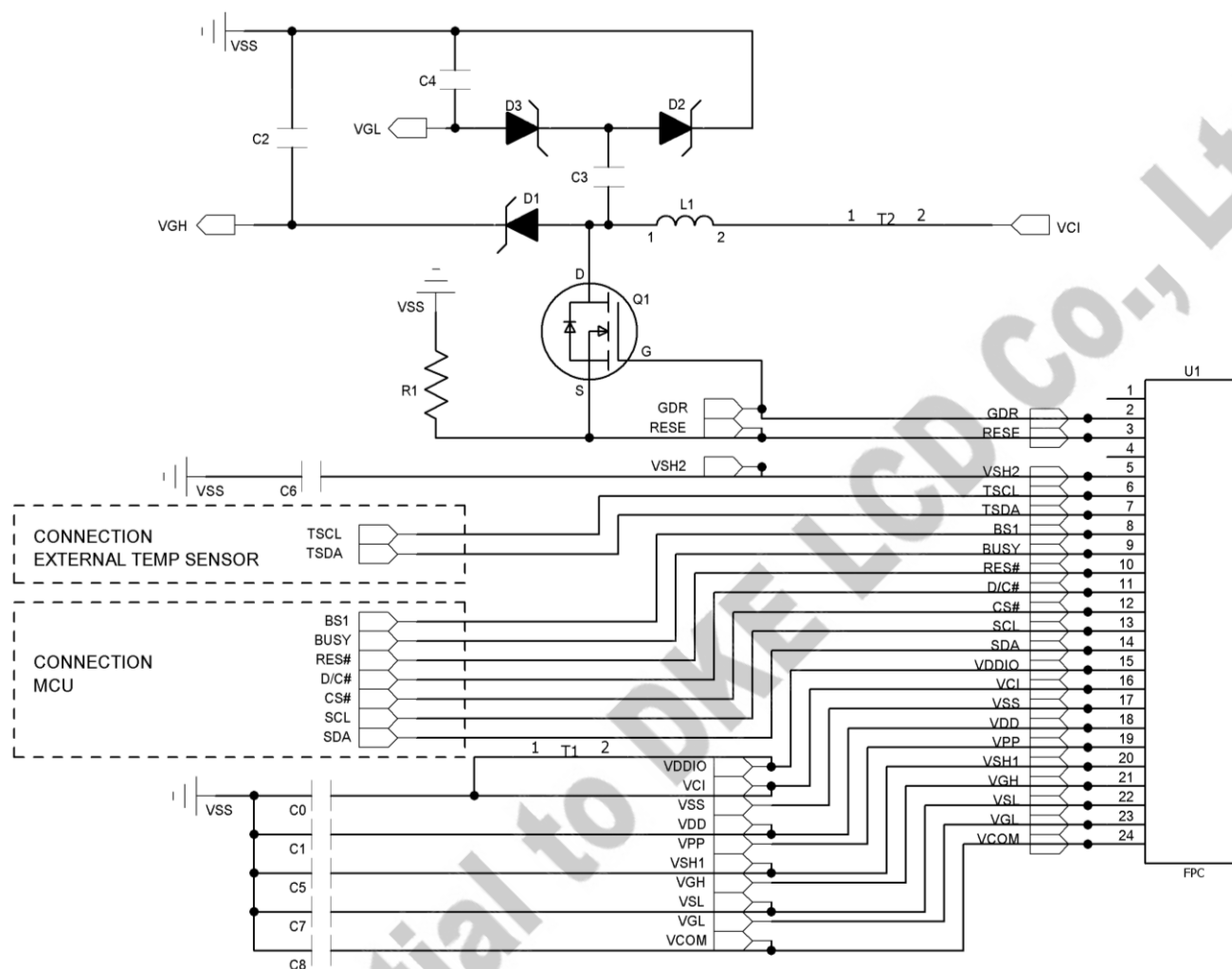


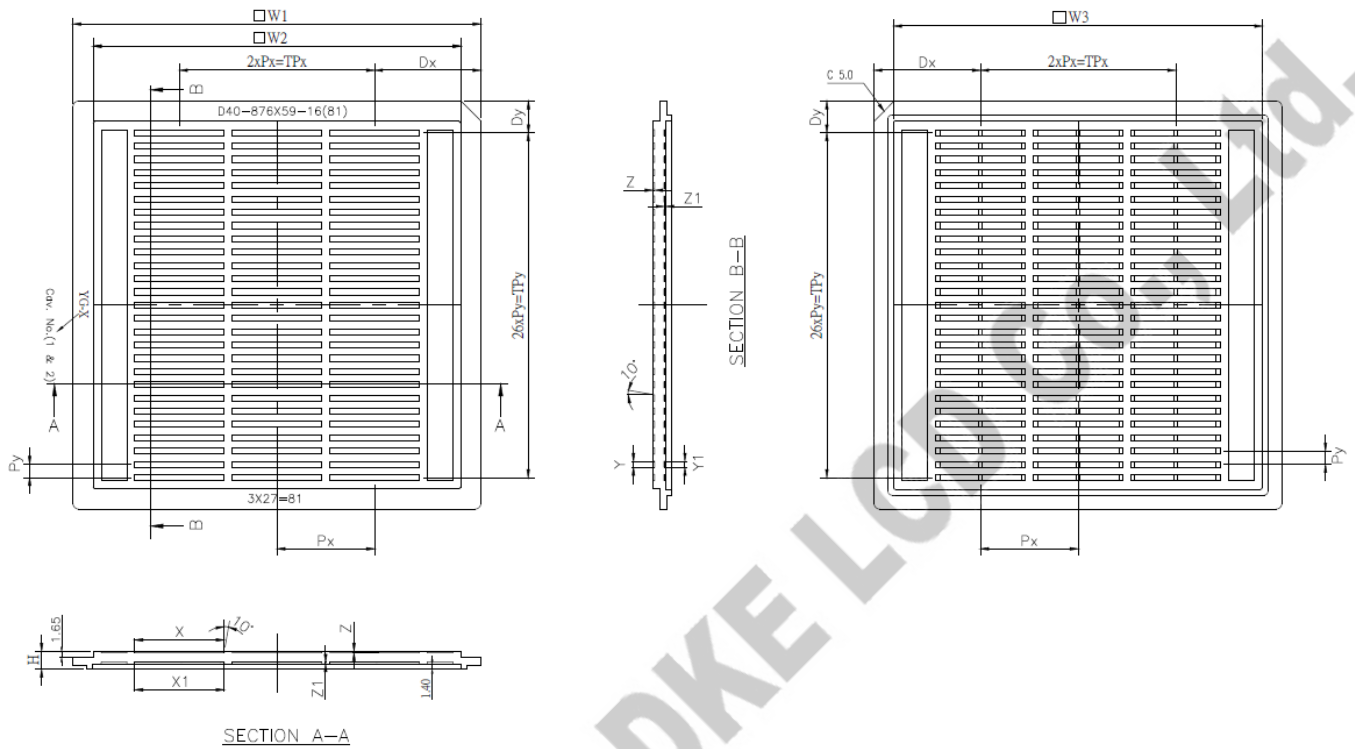
Table 13-1: Component list for SSD1677 application circuit

Part Name	Value	Reference Part/ Requirement
C0-C1	1uF	0603; X5R/X7R; Voltage Rating: 6V
C2-C7	4.7uF	0805; X5R/X7R; Voltage Rating: 25V
C8	1uF	0805; X7R; Voltage Rating: 25V
R1	2.2 Ohm	0805; 1%
D1-D3	Diode	MBR0530
Q1	NMOS	Si1304BDL
L1	47uH	CDRH2D18/ LDNP-470NC
U1	0.5mm ZIF socket	24pins, 0.5mm pitch

Remark: Component value is subjected to change and depends on panel loading.

14 Package Information

Figure 14-1 : SSD1677Z and SSD1677Z8 tray information



Symbol	Spec (mm)
W1	101.60±0.10
W2	91.55±0.10
W3	91.85±0.10
H	4.55±0.10
Dx	26.50±0.05
TPx	48.60±0.10
Dy	7.90±0.05
Tpy	85.80±0.10
Px	24.30±0.05
Py	3.30±0.05
X	22.25±0.05
Y	1.51±0.05
Z	0.40±0.05
X1	22.25±0.05
Y1	1.51±0.05
Z1	0.35±0.05
N	81 (pocket number)

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